

16-Channel, Constant-Current LED Driver with 7-Bit Global Brightness Control, Power-Save Mode, and Full Self-Diagnosis for LED Lamp

Check for Samples: [TLC5929](#)

FEATURES

- 16 Constant-Current Sink Output Channels with On/Off Control
- Current Capability:
 - 40 mA ($V_{CC} \leq 3.6$ V)
 - 50 mA ($V_{CC} > 3.6$ V)
- Global Brightness Control: 7-Bit (128 Steps)
- Power-Supply Voltage Range: 3.0 V to 5.5 V
- LED Power-Supply Voltage: Up to 10 V
- Constant-Current Accuracy:
 - Channel-to-Channel = $\pm 1\%$ (typ), $\pm 3\%$ (max)
 - Device-to-Device = $\pm 2\%$ (typ), $\pm 4\%$ (max)
- Data Transfer Rate: 33 MHz
- BLANK Pulse Width: 40 ns (min)
- LED Open Detection (LOD)/LED Short Detection (LSD) with Invisible Detection Mode (IDM)
- Output Leakage Detection (OLD) Detects 3 μ A Leak
- Pre-Thermal Warning (PTW)
- Thermal Shutdown (TSD)
- Current Reference Terminal Short Flag (ISF)
- Power-Save Mode with 10- μ A Consumption
- Undervoltage Lockout Sets the Default Data

- 2-ns Delayed Switching Between Each Channel Minimizes Inrush Current
- Operating Temperature: -40°C to $+85^{\circ}\text{C}$

APPLICATIONS

- Variable Message Signs (VMS)
- Illumination

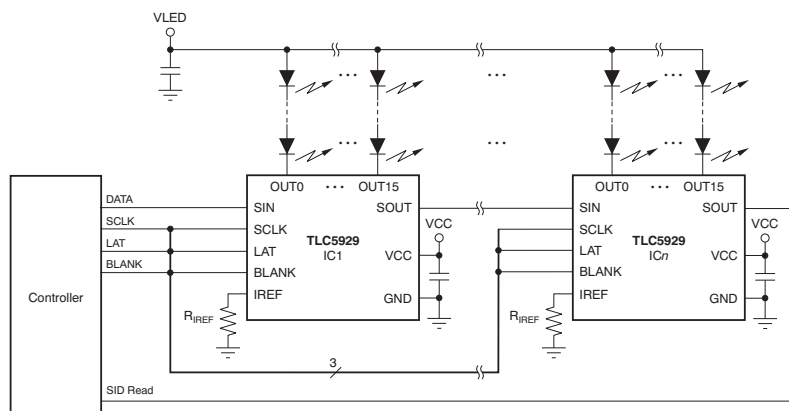
DESCRIPTION

The TLC5929 is a 16-channel constant current sink LED driver. Each channel can be turned on or off by writing data to an internal register. The constant current value of all 16 channels is set by a single external resistor with 128 steps for the global brightness control (BC).

The TLC5929 has six error flags: LED open detection (LOD), LED short detection (LSD), output leakage detection (OLD), reference current terminal short detection (ISF), pre-thermal warning (PTW) and thermal error flag (TEF). In addition, the LOD and LSD functions have invisible detection mode (IDM) that can detect those errors even when the output is off. The error detection results can be read via a serial interface port.

The TLC5929 also has a power-save mode that sets the total current consumption to 10 μ A (typ) when all outputs are off.

Typical Application Circuit (Multiple Daisy-Chaind TLC5929s)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PowerPAD is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

Copyright © 2011–2012, Texas Instruments Incorporated



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION⁽¹⁾

PRODUCT	PACKAGE-LEAD	PACKAGE DESIGNATOR	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
TLC5929	SSOP/QSOP-24	DBQ	TLC5929DBQR	Tape and Reel, 2500
			TLC5929DBQ	Tube, 50
	HTSSOP-24 PowerPAD™	PWP	TLC5929PWPR	Tape and Reel, 2000
			TLC5929PWP	Tube, 60
	QFN-24	RGE	TLC5929RGER	Tape and Reel, 3000
			TLC5929RGE	Tape and Reel, 250

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or visit the device product folder at www.ti.com.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		VALUE		UNIT
		MIN	MAX	
Voltage ⁽²⁾	VCC	−0.3	+6.0	V
	SIN, SCLK, LAT, BLANK, IREF, SOUT	−0.3	V _{CC} + 0.3	V
	OUT0 to OUT15	−0.3	+11	V
Current	OUT0 to OUT15	0	+65	mA
Temperature	Operating junction, T _J (max)	−40	+150	°C
	Storage, T _{STG}	−55	+150	°C
Electrostatic Discharge Ratings	Human body model (HBM)		4000	V
	Charged device model (CDM)		2000	V

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltages are with respect to device ground terminal.

THERMAL INFORMATION

THERMAL METRIC ⁽¹⁾		TLC5929			UNITS
		DBQ	PWP	RGE	
		24 PINS	24 PINS	24 PINS	
θ _{JA}	Junction-to-ambient thermal resistance	85.3	37.6	38.1	°C/W
θ _{JCTop}	Junction-to-case (top) thermal resistance	48.8	24.5	45.3	
θ _{JB}	Junction-to-board thermal resistance	38.6	11.5	16.9	
ψ _{JT}	Junction-to-top characterization parameter	11.9	0.5	0.9	
ψ _{JB}	Junction-to-board characterization parameter	38.3	11.3	16.9	
θ _{JCbot}	Junction-to-case (bottom) thermal resistance	N/A	5.7	6.2	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](http://www.ti.com).

RECOMMENDED OPERATING CONDITIONS

At $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, unless otherwise noted.

PARAMETER		TEST CONDITIONS	TLC5929			UNIT
			MIN	NOM	MAX	
DC Characteristics: V _{CC} = 3 V to 5.5 V						
V _{CC}	Supply voltage		3.0	3.3	5.5	V
V _O	Voltage applied to output	OUT0 to OUT15			10	V
V _{IH}	High-level input voltage	SIN, SCLK, LAT, BLANK	0.7 × V _{CC}		V _{CC}	V
V _{IL}	Low-level input voltage	SIN, SCLK, LAT, BLANK	GND		0.3 × V _{CC}	V
I _{OH}	High-level output current	SOUT			−2	mA
I _{OL}	Low-level output current	SOUT			2	mA
I _{OLC}	Constant output sink current	OUT0 to OUT15, 3 V ≤ V _{CC} < 3.6 V			40	mA
		OUT0 to OUT15, 3.6 V ≤ V _{CC} < 5.5 V			50	mA
T _A	Operating free-air temperature range		−40		+85	°C
T _J	Operating junction temperature range		−40		+125	°C
AC Characteristics: V _{CC} = 3 V to 5.5 V						
f _{CLK} (SCLK)	Data shift clock frequency	SCLK			33	MHz
t _{WH0}	Pulse duration (see Figure 4 and Figure 6)	SCLK	10			ns
t _{WL0}		SCLK	10			ns
t _{WH1}		LAT	20			ns
t _{WH2}		BLANK	40			ns
t _{WL2}		BLANK	40			ns
t _{SU0}		Setup time	SIN to SCLK↑	5		
t _{SU1}	(see Figure 4 and Figure 6)	LAT↑ to SCLK↑	200			ns
t _{H0}	Hold time	SIN to SCLK↑	3			ns
t _{H1}	(see Figure 4 and Figure 6)	LAT↑ to SCLK↑	10			ns

ELECTRICAL CHARACTERISTICS

At $V_{CC} = 3\text{ V}$ to 5.5 V and $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$. Typical values at $V_{CC} = 3.3\text{ V}$ and $T_A = +25^\circ\text{C}$, unless otherwise noted.

PARAMETER		TEST CONDITIONS	TLC5929			UNIT
			MIN	TYP	MAX	
V_{OH}	High-level output voltage	$I_{OH} = -2\text{ mA}$ at SOUT	$V_{CC} - 0.4$			V
V_{OL}	Low-level output voltage	$I_{OL} = 2\text{ mA}$ at SOUT	0.4			V
V_{LOD}	LED open detection threshold	All $OUTn = \text{on}$	0.25	0.30	0.35	V
V_{LSD0}	LED short detection threshold	All $OUTn = \text{on}$, detection voltage code = 0h	$0.32 \times V_{CC}$	$0.35 \times V_{CC}$	$0.38 \times V_{CC}$	V
V_{LSD1}		All $OUTn = \text{on}$, detection voltage code = 1h	$0.42 \times V_{CC}$	$0.45 \times V_{CC}$	$0.48 \times V_{CC}$	V
V_{LSD2}		All $OUTn = \text{on}$, detection voltage code = 2h	$0.52 \times V_{CC}$	$0.55 \times V_{CC}$	$0.58 \times V_{CC}$	V
V_{LSD3}		All $OUTn = \text{on}$, detection voltage code = 3h	$0.62 \times V_{CC}$	$0.65 \times V_{CC}$	$0.68 \times V_{CC}$	V
V_{IREF}	Reference voltage output	$R_{IREF} = 1.3\text{ k}\Omega$	1.175	1.205	1.235	V
I_{IN}	Input current	$V_{IN} = V_{CC}$ or GND at SIN, SCLK, LAT, and BLANK	-1			μA
I_{CC0}	Supply current (V_{CC})	SIN/SCLK/LAT = low, BLANK = high, all $OUTn = \text{off}$, $V_{OUTn} = 0.8\text{ V}$, BC = 7Fh, $R_{IREF} = \text{open}$	2			mA
I_{CC1}		SIN/SCLK/LAT = low, BLANK = high, all $OUTn = \text{off}$, $V_{OUTn} = 0.8\text{ V}$, BC = 7Fh, $R_{IREF} = 3.6\text{ k}\Omega$ ($I_{OUT} = 18.3\text{ mA}$ target)	5			mA
I_{CC2}		SIN/SCLK/LAT/BLANK = low, All $OUTn = \text{on}$, $V_{OUTn} = 0.8\text{ V}$, BC = 7Fh, $R_{IREF} = 3.6\text{ k}\Omega$ ($I_{OUT} = 18.3\text{ mA}$ target)	5			mA
I_{CC3}		SIN/SCLK/LAT/BLANK = low, All $OUTn = \text{on}$, $V_{OUTn} = 0.8\text{ V}$, BC = 7Fh, $R_{IREF} = 1.6\text{ k}\Omega$ ($I_{OUT} = 41.3\text{ mA}$ target)	9			mA
I_{CC4}		$V_{CC} = 5.0\text{ V}$, SIN/SCLK/LAT/BLANK = low, All $OUTn = \text{on}$, $V_{OUTn} = 0.8\text{ V}$, BC = 7Fh, $R_{IREF} = 1.3\text{ k}\Omega$ ($I_{OUT} = 50.8\text{ mA}$ target)	11			mA
I_{CC5}		$V_{CC} = 5.0\text{ V}$, SIN/SCLK/LAT/BLANK = low, All $OUTn = \text{on}$, $V_{OUTn} = 0.8\text{ V}$, BC = 7Fh, $R_{IREF} = 1.3\text{ k}\Omega$ ($I_{OUT} = 50.8\text{ mA}$ target), all output data off with power-save mode enabled	10			μA
I_{OLC0}	Constant output sink current (OUT0 to OUT15, see Figure 3)	All $OUTn = \text{on}$, $V_{OUTn} = V_{OUTfix} = 0.8\text{ V}$, BC = 7Fh, $R_{IREF} = 1.6\text{ k}\Omega$	38.5	41.3	44.1	mA
I_{OLC1}		$V_{CC} = 5.0\text{ V}$, All $OUTn = \text{on}$, $V_{OUTn} = V_{OUTfix} = 1\text{ V}$, BC = 7Fh, $R_{IREF} = 1.3\text{ k}\Omega$	47.3	50.8	54.3	mA
I_{OLKG0}	Output leakage current (OUT0 to OUT15, see Figure 3)	BLANK = high, $V_{OUTn} = V_{OUTfix} = 10\text{ V}$, $R_{IREF} = 1.6\text{ k}\Omega$	$T_J = +25^\circ\text{C}$		0.1	μA
I_{OLKG1}			$T_J = +85^\circ\text{C}^{(1)}$		0.2	μA
I_{OLKG2}			$T_J = +125^\circ\text{C}^{(1)}$		0.3	μA
ΔI_{OLC0}	Constant-current error (channel-to-channel, OUT0 to OUT15) ⁽²⁾	All $OUTn = \text{on}$, $V_{OUTn} = V_{OUTfix} = 0.8\text{ V}$, BC = 7Fh, $R_{IREF} = 1.6\text{ k}\Omega$, $T_A = +25^\circ\text{C}$	± 1		± 3	%
ΔI_{OLC1}	Constant-current error (device-to-device, OUT0 to OUT15) ⁽³⁾	All $OUTn = \text{on}$, $V_{OUTn} = V_{OUTfix} = 0.8\text{ V}$, BC = 7Fh, $R_{IREF} = 1.6\text{ k}\Omega$, $T_A = +25^\circ\text{C}$	± 2		± 4	%

(1) Not tested; specified by design.

(2) The deviation of each output from the average of OUT0 to OUT15 constant-current. Deviation is calculated by the formula:

$$\Delta (\%) = 100 \times \left[\frac{\frac{I_{OLC(n)}}{(I_{OLC(0)} + I_{OLC(1)} + \dots + I_{OLC(14)} + I_{OLC(15)})} - 1}{16} \right]$$

(3) The deviation of the OUT0 to OUT15 constant-current average from the ideal constant-current value. Deviation is calculated by the formula:

$$\Delta (\%) = 100 \times \left[\frac{\frac{(I_{OLC(0)} + I_{OLC(1)} + \dots + I_{OLC(14)} + I_{OLC(15)})}{16}}{\text{Ideal Output Current}} - (\text{Ideal Output Current}) \right]$$

Ideal current is calculated by the formula:

$$I_{OLC(\text{IDEAL})} = 54.8 \times \left[\frac{1.205}{R_{IREF}} \right]$$

ELECTRICAL CHARACTERISTICS (continued)

At $V_{CC} = 3\text{ V}$ to 5.5 V and $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$. Typical values at $V_{CC} = 3.3\text{ V}$ and $T_A = +25^\circ\text{C}$, unless otherwise noted.

PARAMETER		TEST CONDITIONS	TLC5929			UNIT
			MIN	TYP	MAX	
ΔI_{OLC2}	Line regulation ⁽⁴⁾	All $OUTn = \text{on}$, $V_{OUTn} = V_{OUTix} = 0.8\text{ V}$, $BC = 7\text{Fh}$, $R_{IREF} = 1.6\text{ k}\Omega$		± 0.1	± 1	%/V
ΔI_{OLC3}	Load regulation ⁽⁵⁾	All $OUTn = \text{on}$, $V_{OUTn} = 0.8\text{ V}$ to 3 V , $V_{OUTix} = 0.8\text{ V}$, $BC = 7\text{Fh}$, $R_{IREF} = 1.6\text{ k}\Omega$		± 0.5	± 3	%/V
T_{TEF}	Thermal error flag threshold	Junction temperature ⁽⁶⁾	150	165	180	$^\circ\text{C}$
T_{HYS}	Thermal error flag hysteresis	Junction temperature ⁽⁶⁾	5	10	20	$^\circ\text{C}$
T_{PTW}	Pre-thermal warning threshold	Junction temperature ⁽⁶⁾	125	138	150	$^\circ\text{C}$

(4) Line regulation is calculated by the formula:

$$\Delta (\%) = 100 \times \left(\frac{(I_{OLC(n)} \text{ at } V_{CC} = 5.5\text{ V}) - (I_{OLC(n)} \text{ at } V_{CC} = 3.0\text{ V})}{2.5 \times (I_{OLC(n)} \text{ at } V_{CC} = 3.0\text{ V})} \right)$$

Where 2.5 is the difference between the maximum and minimum V_{CC} voltage.

(5) Load regulation is calculated by the equation:

$$\Delta (\%) = 100 \times \left(\frac{(I_{OLC(n)} \text{ at } V_{OUTn} = 3\text{ V}) - (I_{OLC(n)} \text{ at } V_{OUTn} = 0.8\text{ V})}{2.2 \times (I_{OLC(n)} \text{ at } V_{OUTn} = 0.8\text{ V})} \right)$$

Where 2.2 is the difference between the maximum and minimum V_{CC} voltage.

(6) Not tested; specified by design.

SWITCHING CHARACTERISTICS (See [Figure 1](#), [Figure 2](#), and [Figure 5](#) through [Figure 7](#))

At $V_{CC} = 3\text{ V}$ to 5.5 V , $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$, $C_L = 15\text{ pF}$, $R_L = 82\text{ }\Omega$, $R_{IREF} = 1.3\text{ k}\Omega$, and $V_{LED} = 5.0\text{ V}$.

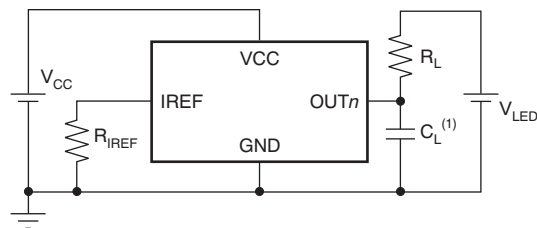
Typical values at $V_{CC} = 3.3\text{ V}$ and $T_A = +25^\circ\text{C}$, unless otherwise noted.

PARAMETER		TEST CONDITIONS	TLC5929			UNIT
			MIN	TYP	MAX	
t_{R0}	Rise time	SOUT		3	10	ns
t_{R1}		$OUTn$, $BC = 7\text{Fh}$, $T_A = +25^\circ\text{C}$		23	60	ns
t_{F0}	Fall time	SOUT		3	10	ns
t_{F1}		$OUTn$, $BC = 7\text{Fh}$, $T_A = +25^\circ\text{C}$		31	60	ns
t_{D0}	Propagation delay	$SCLK\uparrow$ to $SOUT\uparrow\downarrow$		15	25	ns
t_{D1}		$LAT\uparrow$ or $BLANK\uparrow\downarrow$ to $OUT0$ sink current on/off, $BC = 7\text{Fh}$		35	65	ns
t_{D2}		$OUTn$ on/off to $OUTn + 1$ on/off, $BC = 7\text{Fh}$		3	11	ns
t_{D3}		$LAT\uparrow$ to power-save mode by data writing for all output off			300	ns
t_{D4}		$SCLK\uparrow$ to normal mode operation			20	μs
t_{ON_ERR}	Output on-time error ⁽¹⁾	Output on/off data = all '1', $BLANK$ low pulse = 40 ns , $BC = 7\text{Fh}$	-30		20	ns
f_{OSC}	Internal oscillator frequency		12	20	28	MHz

(1) Output on-time error (t_{ON_ERR}) is calculated by the formula: $t_{ON_ERR} (\text{ns}) = t_{OUT_ON} - 40\text{ ns}$. t_{OUT_ON} is the actual on-time of $OUTn$.

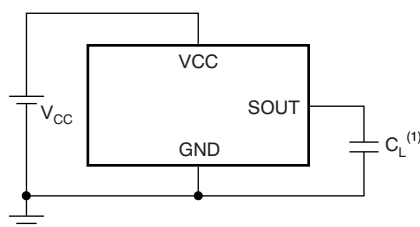
PARAMETER MEASUREMENT INFORMATION

TEST CIRCUITS



(1) C_L includes measurement probe and jig capacitance.

Figure 1. Rise Time and Fall Time Test Circuit for OUTn



(1) C_L includes measurement probe and jig capacitance.

Figure 2. Rise Time and Fall Time Test Circuit for SOUT

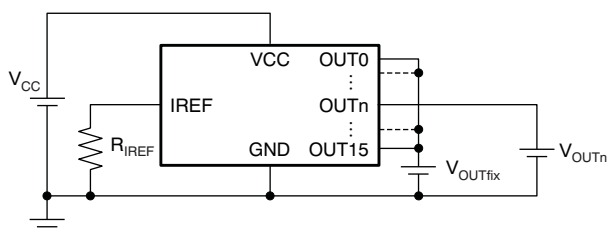
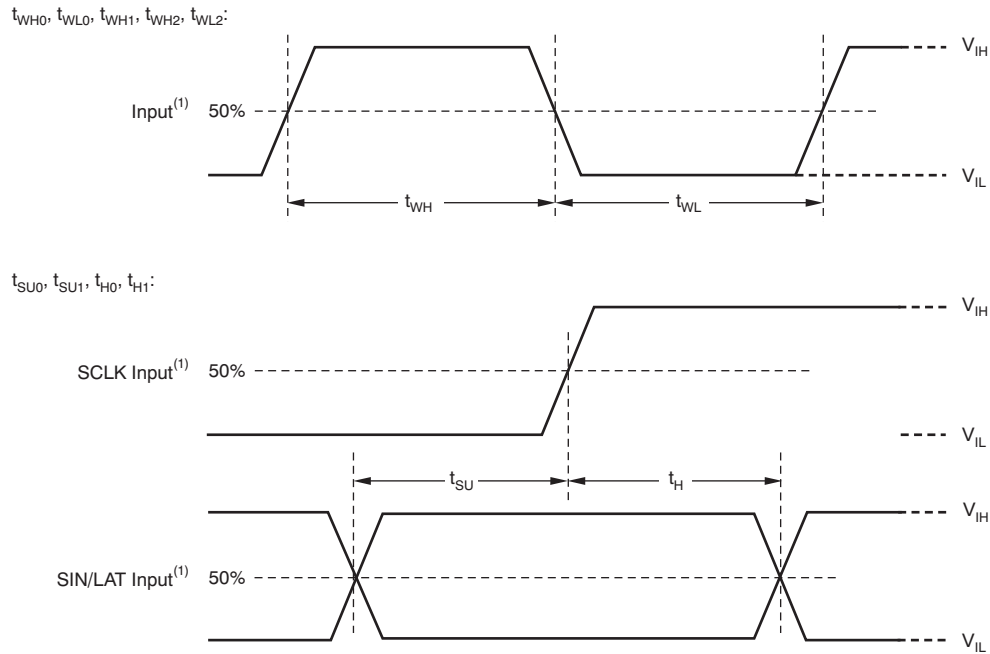


Figure 3. Constant-Current Test Circuit for OUTn

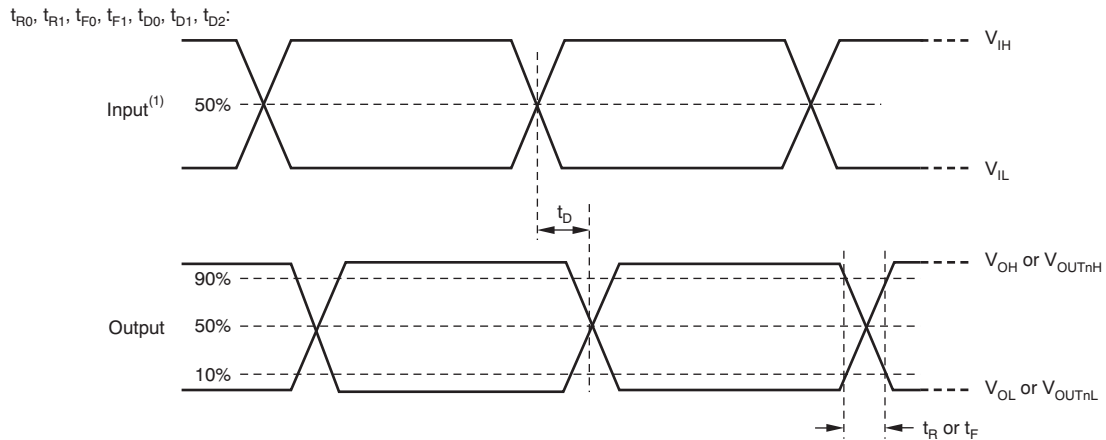
PARAMETER MEASUREMENT INFORMATION (continued)

TIMING DIAGRAMS



(1) Input pulse rise and fall time is 1 ns to 3 ns.

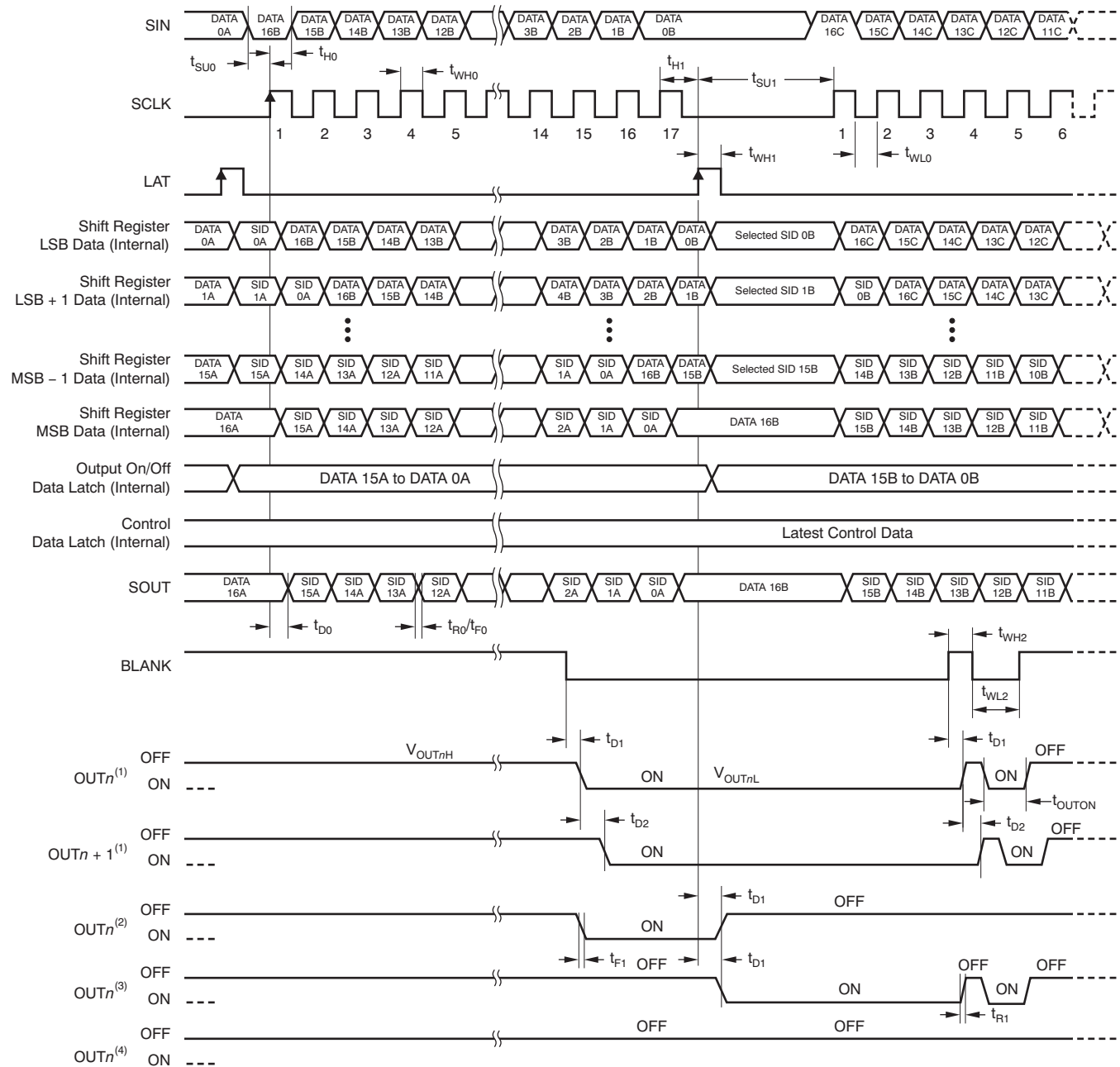
Figure 4. Input Timing



(1) Input pulse rise and fall time is 1 ns to 3 ns.

Figure 5. Output Timing

PARAMETER MEASUREMENT INFORMATION (continued)



- (1) On/off latched data is '1'.
- (2) On/off latched data change from '1' to '0' at second LAT signal.
- (3) On/off latched data change from '0' to '1' at second LAT signal.
- (4) On/off latched data is '0'.

Figure 6. Write for On/Off Data and Output Timing

PARAMETER MEASUREMENT INFORMATION (continued)

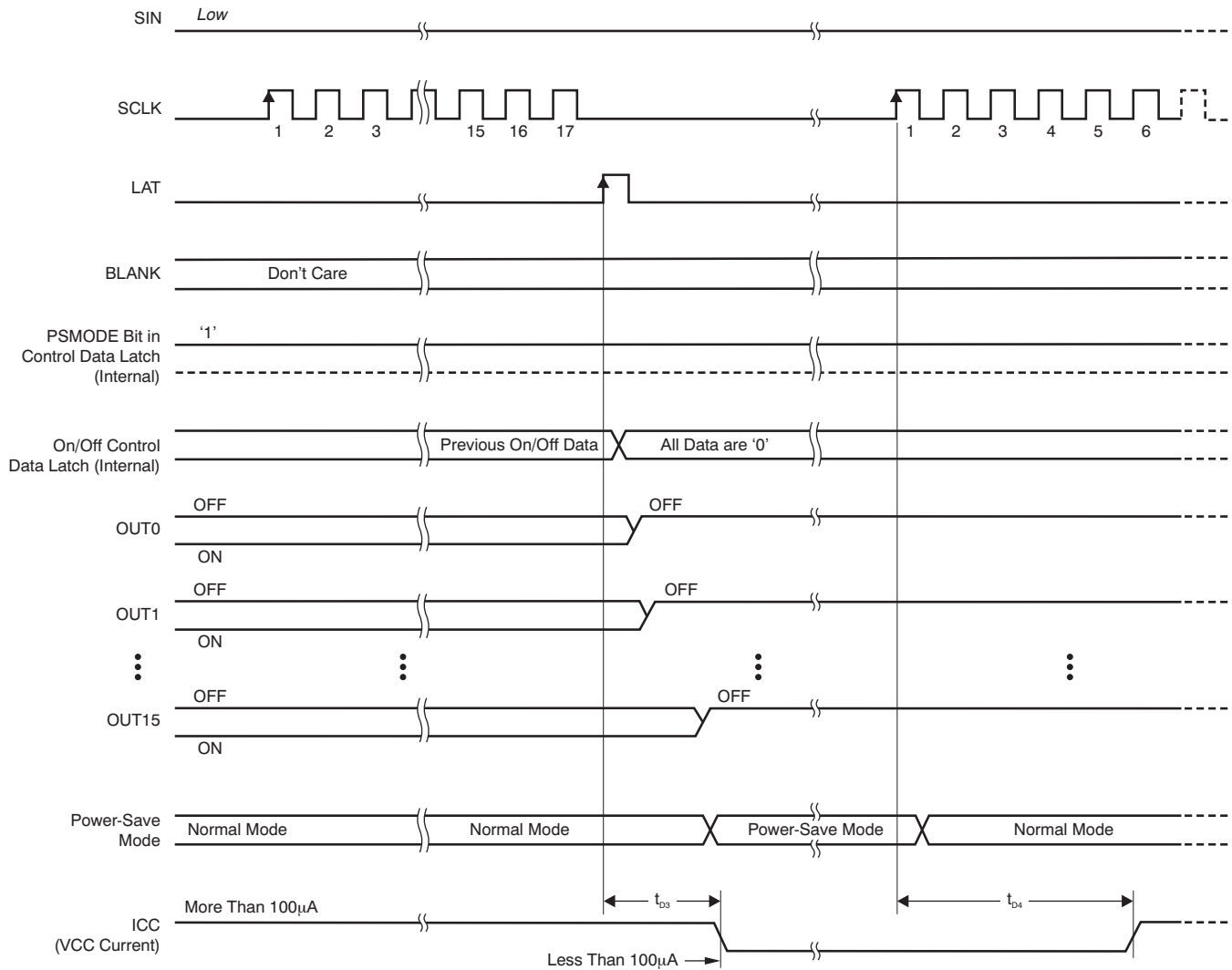
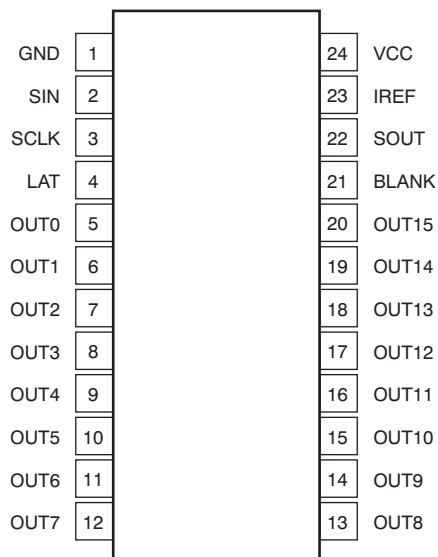


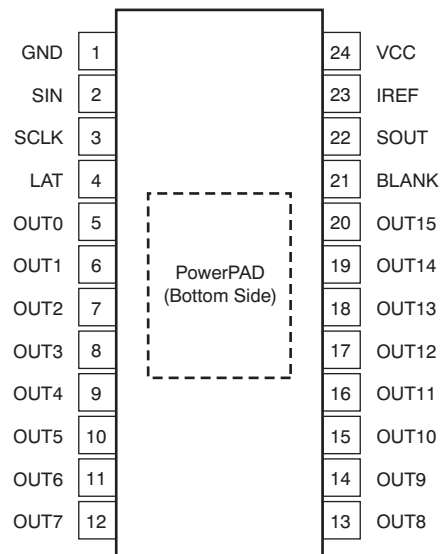
Figure 7. Power-Save Mode Timing

PIN CONFIGURATIONS

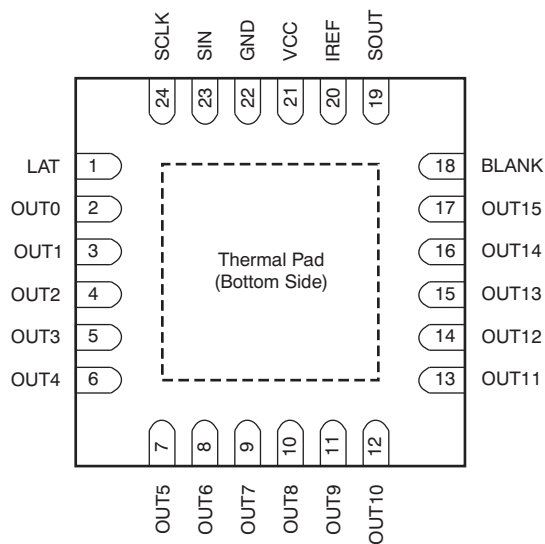
**SSOP/QSOP-24
DBQ PACKAGE
(TOP VIEW)**



**HTSSOP-24
PWP PACKAGE
(TOP VIEW)**



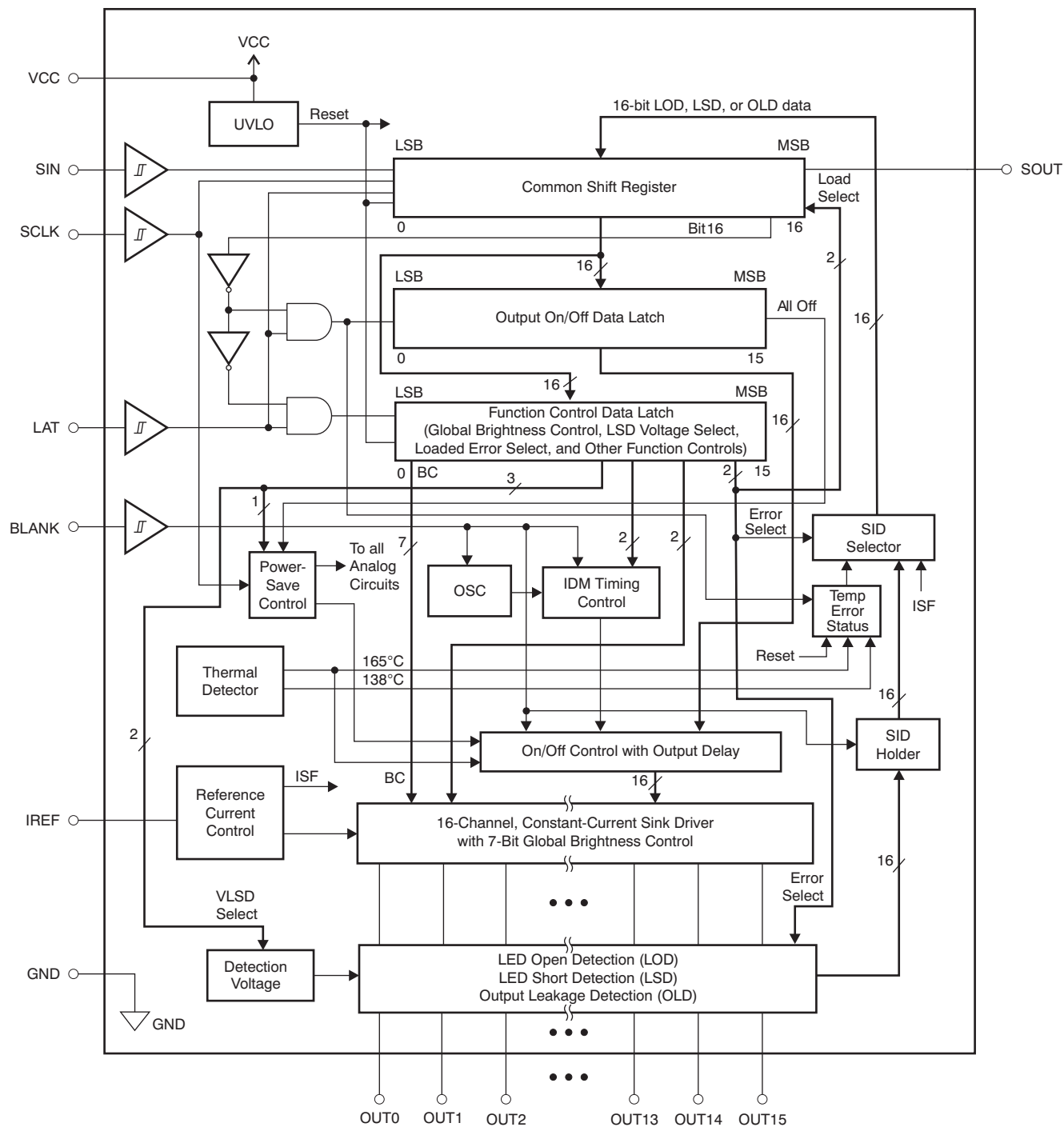
**QFN-24
RGE PACKAGE
(TOP VIEW)**



PIN DESCRIPTIONS

PIN			I/O	DESCRIPTION
NAME	DBQ/PWP	RGE		
BLANK	21	18	I	Blank all outputs. When BLANK is high, all constant-current outputs (OUT0 to OUT15) are forced off. When BLANK is low, all constant-current outputs are controlled by the on/off control data in the data latch.
GND	1	22	—	Ground
IREF	23	20	I/O	Maximum current programming terminal. A resistor connected between IREF and GND sets the maximum current for every constant-current output. When this terminal is directly connected to GND, all outputs are forced off. The external resistor should be placed close to the device and must be in the range of 1.32 kΩ to 66.0 kΩ.
LAT	4	1	I	Data latch. The rising edge of LAT latches the data from the common shift register into the output on/off data latch. At the same time, the data in the common shift register are replaced with SID, which is selected by SIDLD. See the Output On/Off Data Latch section and Status Information Data (SID) section for more details.
OUT0	5	2	O	Constant-current sink outputs. Multiple outputs can be configured in parallel to increase the constant-current capability. Different voltages can be applied to each output.
OUT1	6	3	O	
OUT2	7	4	O	
OUT3	8	5	O	
OUT4	9	6	O	
OUT5	10	7	O	
OUT6	11	8	O	
OUT7	12	9	O	
OUT8	13	10	O	
OUT9	14	11	O	
OUT10	15	12	O	
OUT11	16	13	O	
OUT12	17	14	O	
OUT13	18	15	O	
OUT14	19	16	O	
OUT15	20	17	O	
SCLK	3	24	I	Serial data shift clock. Data present on SIN are shifted to the LSB of the 17-bit shift register with the SCLK rising edge. Data in the shift register are shifted toward the MSB at each SCLK rising edge. The MSB data of the common shift register appear on SOUT.
SIN	2	23	I	Serial data input for the 17-bit common shift register. When SIN is high, a '1' is written to the LSB of the common shift register at the rising edge of SCLK.
SOUT	22	19	O	Serial data output of the 17-bit common shift register. SOUT is connected to the MSB of the 17-bit shift register. Data are clocked out at the rising edge of SCLK.
VCC	24	21	—	Power-supply voltage

FUNCTIONAL BLOCK DIAGRAM



TYPICAL CHARACTERISTICS

At $T_A = +25^\circ\text{C}$, unless otherwise noted.

**REFERENCE RESISTOR
vs OUTPUT CURRENT**

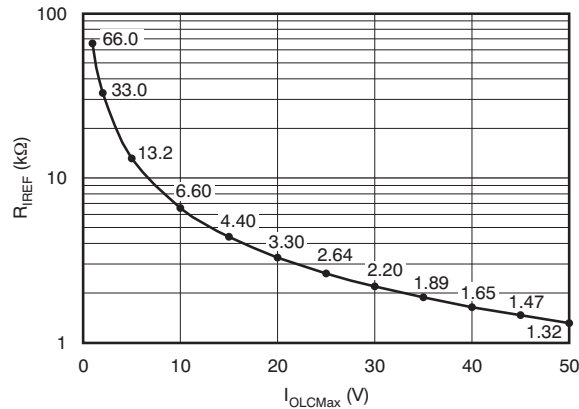


Figure 8.

**OUT_n CURRENT vs
OUTPUT VOLTAGE (+3.3 V)**

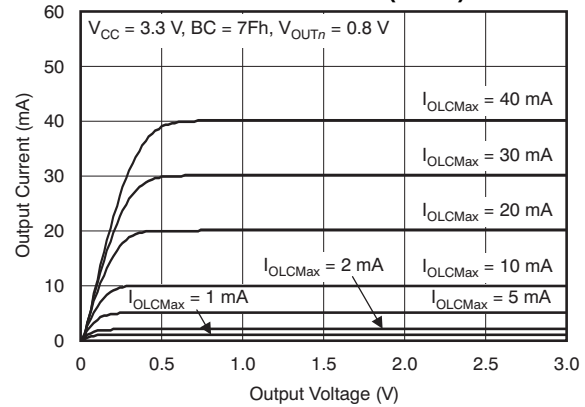


Figure 9.

**OUT_n CURRENT vs
OUTPUT VOLTAGE (+3.3 V)**

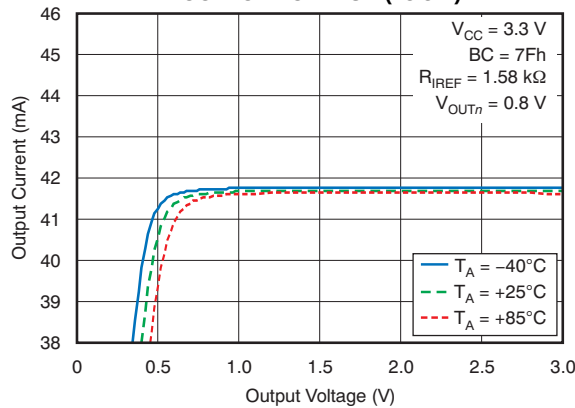


Figure 10.

**OUT_n CURRENT vs
OUTPUT VOLTAGE (+5 V)**

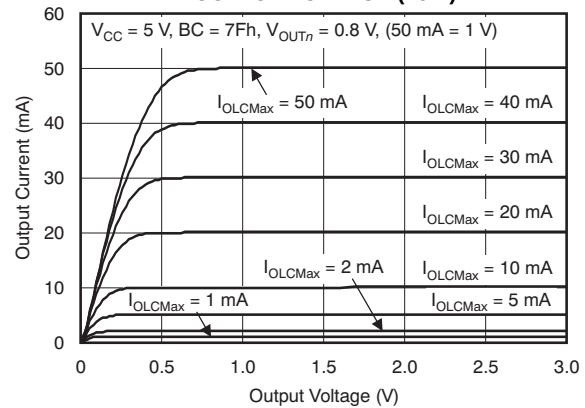


Figure 11.

**OUT_n CURRENT vs
OUTPUT VOLTAGE (+5 V)**

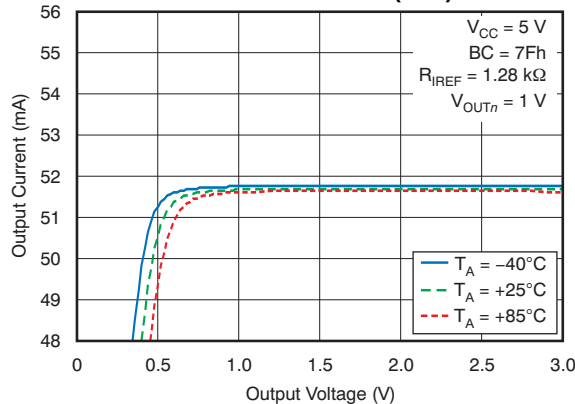


Figure 12.

**CONSTANT-CURRENT ERROR
vs OUTPUT CURRENT SET BY R_{IREF} or BC DATA (Channel-
to-Channel)**

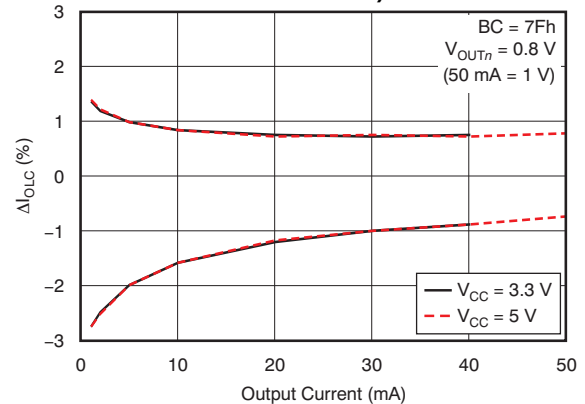


Figure 13.

TYPICAL CHARACTERISTICS (continued)

At $T_A = +25^\circ\text{C}$, unless otherwise noted.

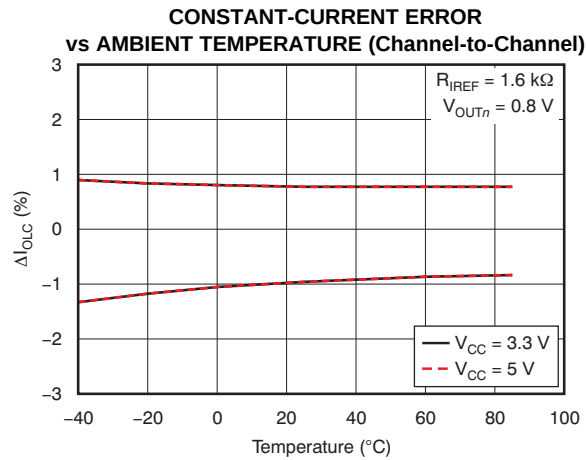


Figure 14.

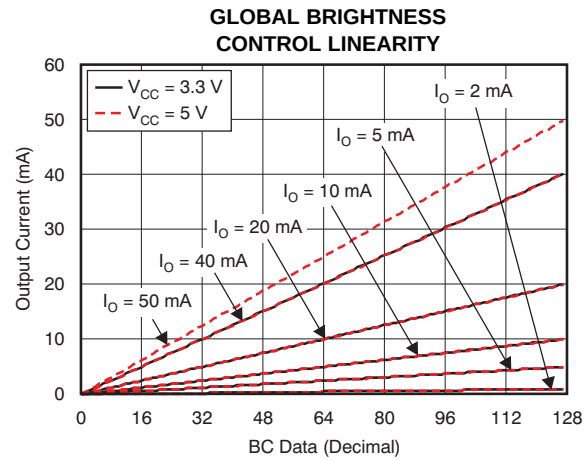


Figure 15.

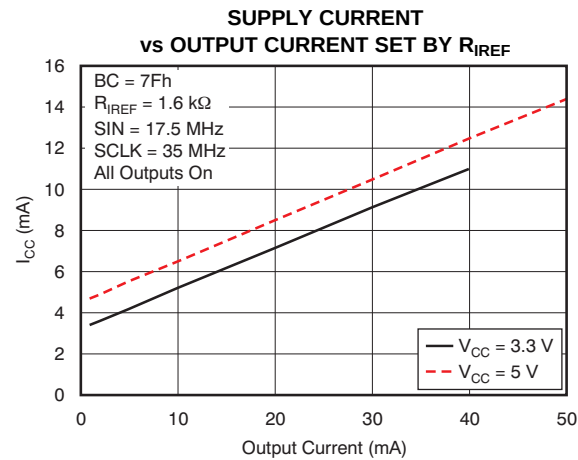


Figure 16.

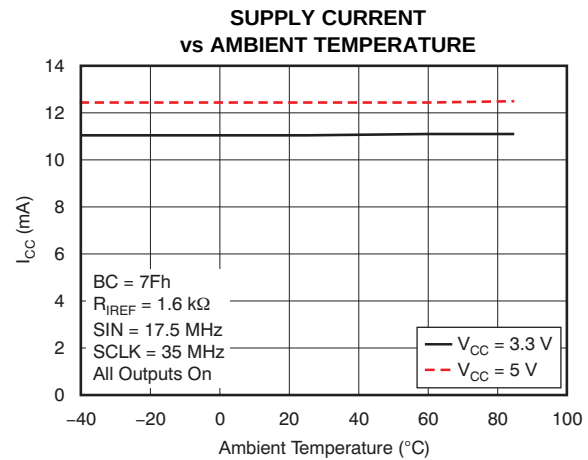


Figure 17.

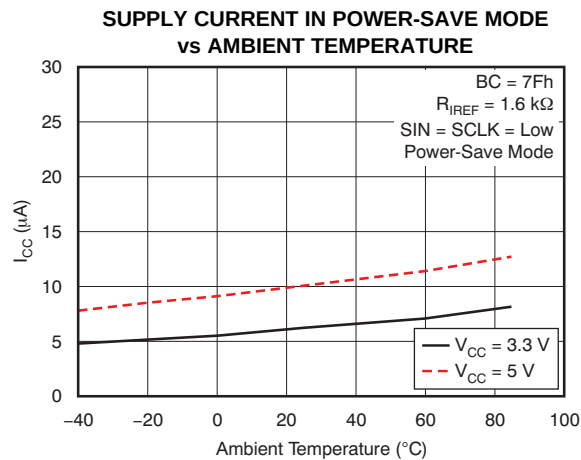


Figure 18.

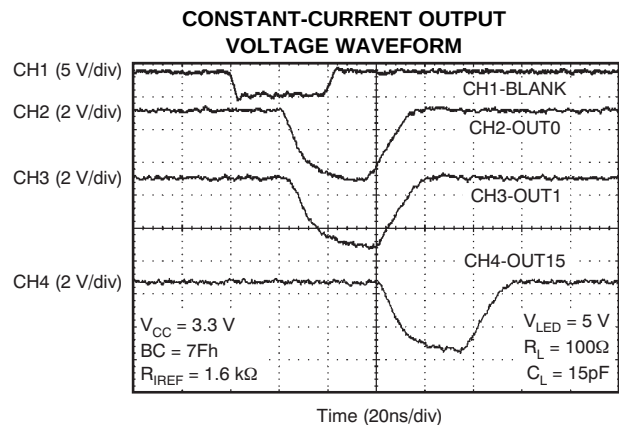


Figure 19.

DETAILED DESCRIPTION

MAXIMUM CONSTANT SINK CURRENT

The maximum output current of each channel ($I_{OLCM_{max}}$) is programmed by a single resistor (R_{IREF}) that is placed between the IREF and GND pins. The current value can be calculated by [Equation 1](#):

$$R_{IREF} = \frac{V_{IREF}}{I_{OLCM_{max}}} \times 54.8$$

Where:

V_{IREF} = the internal reference voltage on IREF (typically 1.205 V when the global brightness control data are at maximum.

$I_{OLCM_{max}}$ = 1 mA to 40 mA for $V_{CC} \leq 3.6$ V, or 1 mA to 50 mA for $V_{CC} > 3.6$ V at OUT0 to OUT15 with BC = 7Fh (1)

$I_{OLCM_{max}}$ is the highest current for each output. Each output sinks $I_{OLCM_{max}}$ current when it is turned on with the maximum global brightness control (BC) data. Each output sink current can be reduced by lowering the global brightness control value. R_{IREF} must be between 1.32 k Ω and 66.0 k Ω in order to hold $I_{OLCM_{max}}$ between 50 mA (typ) and 1 mA (typ). Otherwise, the output may be unstable. Output currents lower than 1 mA can be achieved by setting $I_{OLCM_{max}}$ to 1 mA or higher and then using the global brightness control to lower the output current.

[Figure 8](#) and [Table 1](#) show the characteristics of the constant-current sink versus the external resistor, R_{IREF} .

Table 1. Maximum Constant Current Output versus External Resistor Value

$I_{OLCM_{max}}$ (mA)	R_{IREF} (k Ω , typ)
50 ($V_{CC} > 3.6$ V only)	1.32
45 ($V_{CC} > 3.6$ V only)	1.47
40	1.65
35	1.89
30	2.20
25	2.64
20	3.30
15	4.40
10	6.60
5	13.2
2	33.0
1	66.0

GLOBAL BRIGHTNESS CONTROL (BC) FUNCTION

The TLC5929 has the ability to adjust the output current of all constant current outputs simultaneously. This function is called *global brightness control* (BC). The global BC for all outputs (OUT0 to OUT15) can be set with a 7-bit word. The global BC adjusts all output currents in 128 steps from 0% to 100%, where 100% corresponds to the maximum output current set by R_{IREF} . Equation 2 calculates the actual output current. BC data can be set via the serial interface.

$$I_{OLCn} \text{ (mA)} = \frac{I_{OLCMax} \text{ (mA)} \times BC}{127}$$

Where:

I_{OLCMax} = the maximum constant-current value for each output determined by R_{IREF} .

BC = the global brightness control value in the control data latch (0h to 7Fh) (2)

Table 2 shows the BC data versus the constant-current ratio against I_{OLCMax} .

Table 2. BC Data versus Constant-Current Ratio Against I_{OLCMax}

BC DATA			RATIO OF OUTPUT CURRENT TO I_{OLCMax} (%)	I_{OLC} (mA, I_{OLCMax} = 40mA, typ)	I_{OLC} (mA, I_{OLCMax} = 1mA, typ)
BINARY	DECIMAL	HEX			
000 0000	0	00	0	0	0
000 0001	1	01	0.8	0.31	0.01
000 0010	2	02	1.6	0.63	0.02
...	...	...	...	...	...
111 1101	125	7D	98.4	39.4	0.98
111 1110	126	7E	99.2	39.7	0.99
111 1111	127	7F	100.0	40.0	1.00

REGISTER AND DATA LATCH CONFIGURATION

The TLC5929 has one common shift register and two control data latches. The common shift register is 17-bits long and the two control data latches are 16-bits long. When the MSB of the common shift register is '0' and LAT shows a rising edge, the lower 16 bits of the common shift register are copied into the output on/off data latch. When the MSB is '1' and LAT shows a rising edge, the lower 16 bits are copied into the control data latch. [Figure 20](#) shows the configuration of the common shift register and the two control data latches.

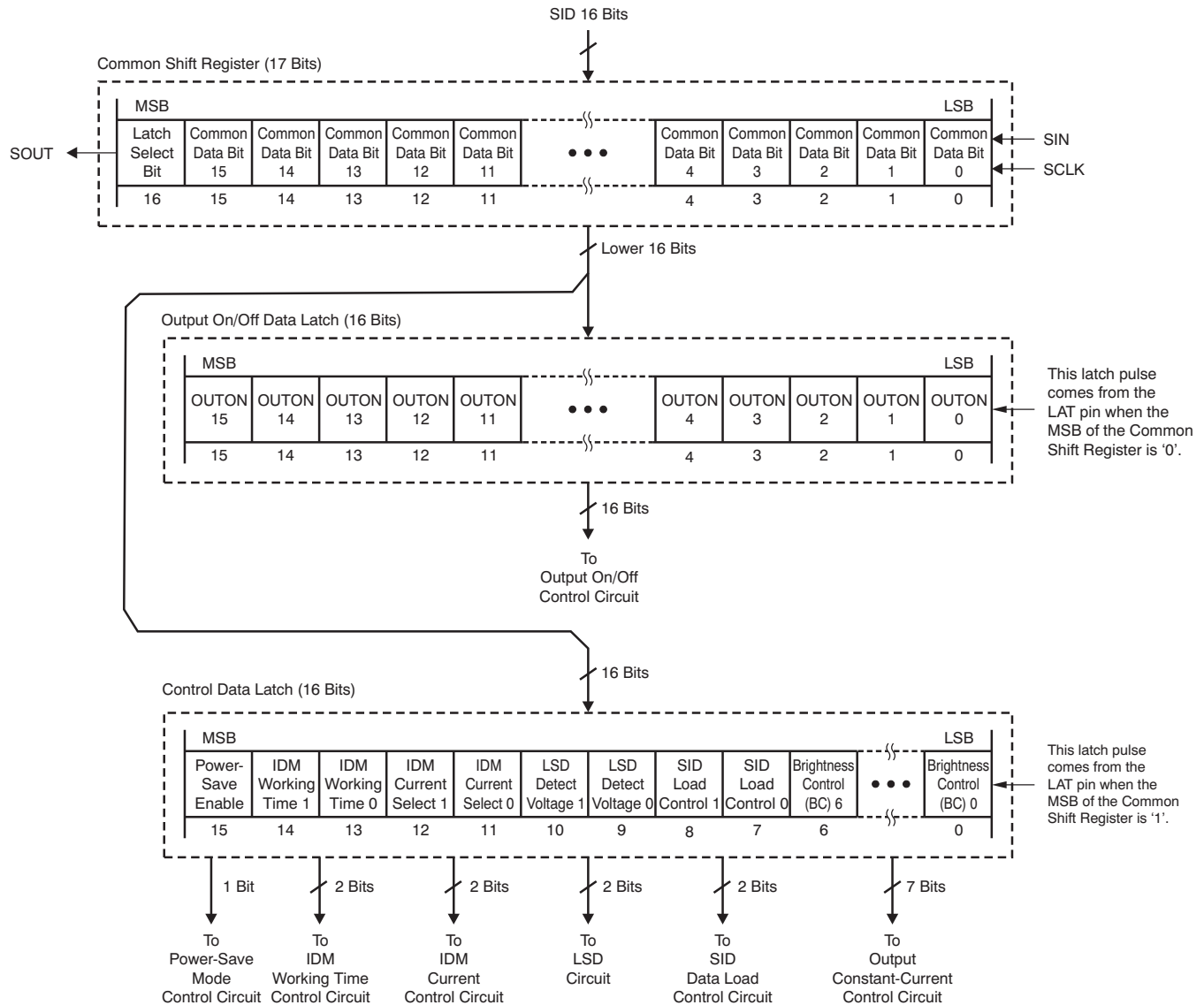


Figure 20. Common Shift Register and Control Data Latches Configuration

Common Shift Register

The 17-bit common shift register is used to shift data from the SIN pin into the TLC5929. The data shifted into the register are used for the output on/off control, global BC, and the control functions. The LSB of the common shift register is connected to SIN and the MSB is connected to SOUT. On each rising edge of SCLK, the data on SIN are shifted into the LSB and all 17 bits are shifted towards the MSB. The register MSB is always connected to SOUT.

In addition, the status information data (SID) selected by the load select data in the control data latch are loaded to the lower 16 bits of the common shift register when a rising edge is input on LAT and the MSB of the shift register is '0'.

When the device is powered on, all 17 bits of the common shift register are set to '0'.

Output On/Off Data Latch

The output on/off data latch is 16 bits long and sets the on or off status for each constant-current output.

When BLANK is low, the output corresponding to the specific bit in the output on/off data latch is turned on if the data is '1' and remains off if the data is '0'. When BLANK is high, all outputs are forced off, but the data in the latch do not change as long as LAT does not latch in new data.

When the device is powered on, all bits in the data latch are set to '0'.

The output on/off data latch configuration is shown in [Figure 21](#) and the data bit assignment is shown in [Table 3](#).

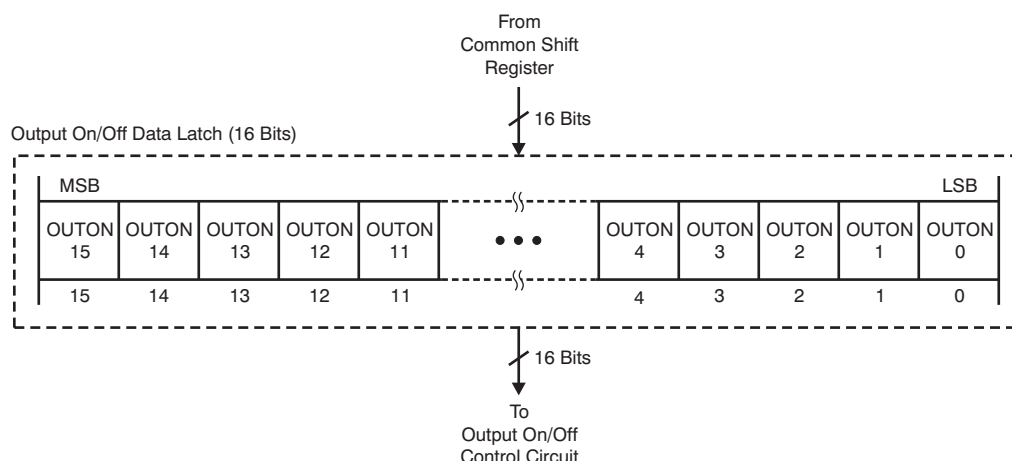


Figure 21. Output On/Off Data Latch Configuration

Table 3. On/Off Control Data Latch Bit Assignment

BIT NUMBER	BIT NAME	CONTROLLED CHANNEL	DESCRIPTION
0	OUTON0	OUT0	'0' = Output off '1' = Output on with BLANK low. When the device is powered on, all bits are set to '0'.
1	OUTON1	OUT1	
2	OUTON2	OUT2	
...	...	...	
13	OUTON13	OUT13	
14	OUTON14	OUT14	
15	OUTON15	OUT15	

Function Control Data Latch

The function control data latch is 16 bits long and contains the global brightness control (BC) data, status information data (SID) load control data, LED short detection (LSD) voltage level data, the current value of the invisible detection mode (IDM), IDM working time, and power-save mode enable control data.

When the device is powered up, the data in this data latch are set to the default values shown in [Table 4](#). This table contains the bit names, numbers and descriptions.

The function control data latch configuration is shown in [Figure 22](#). [Table 4](#) lists the bit descriptions.

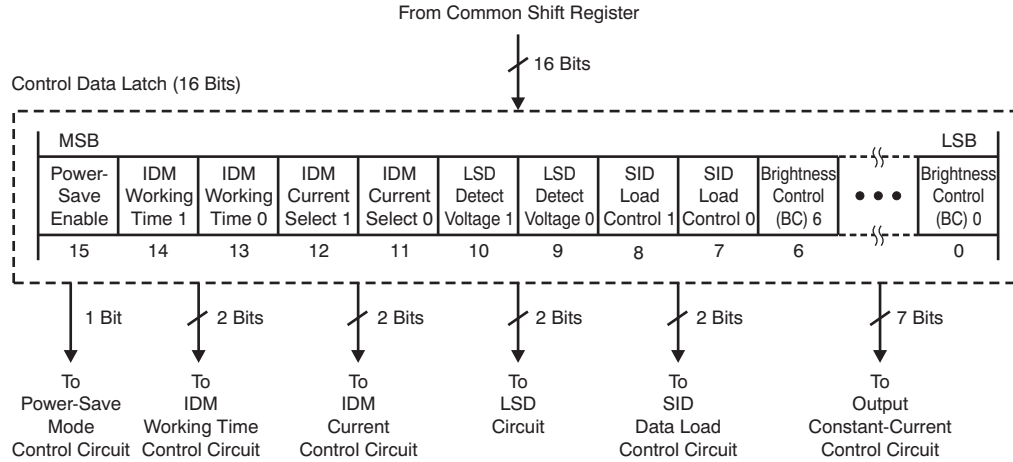


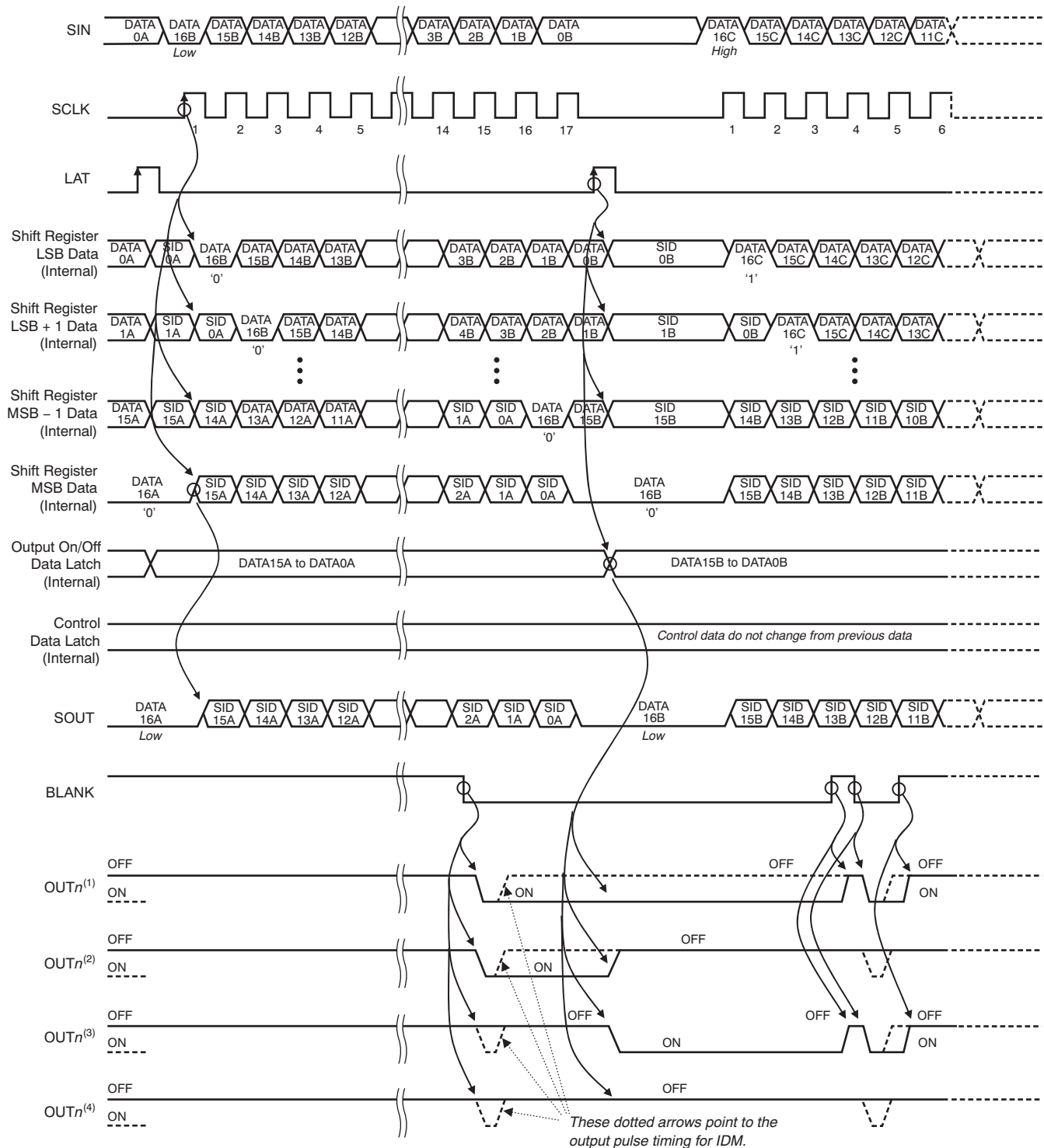
Figure 22. Function Control Data Latch Configuration

Table 4. Function Control Data Latch Bit Description

BIT NUMBER	BIT NAME	DEFAULT VALUE (BINARY)	DESCRIPTION
[6:0]	BCALL	1111111	Global brightness control. These seven bits control the current of all outputs with 128 steps between 0% to 100% of the maximum current value set by the external resistor. Table 2 shows the current value truth table.
[8:7]	SIDLD	00	SID load control. These two bits select the SID loaded to the common register when the LAT pulse is input for on/off data writing (MSB of the common shift register must be '0'). Table 6 shows the selected data truth table.
[10:9]	LSDVLT	11	LSD detection voltage select. These two bits select the detection threshold voltage for the LED short detection (LSD). Table 7 shows the detect voltage truth table.
[12:11]	IDMCUR	00	IDM current select. These two bits select the sink current at OUT _n for the IDM to detect the LED open detection (LOD) or the LED short detection (LSD) without visible lighting. Table 8 shows the current value truth table. Figure 27 and Figure 28 show the IDM operation timing.
[14:13]	IDMTIM	11	IDM working time select. These two bits select the time of the IDMCUR output sink current at OUT _n to detect the LED open detection (LOD) or LED short detection (LSD) without visible light. Table 9 shows the work-time truth table. Figure 27 and Figure 28 show the IDM operation timing.
[15]	PSMODE	1	Power save mode enable. This bit enables or disables the power-save mode. When the mode is enabled (PSMODE = '1'), the device goes into power-save mode if all data in the on/off data latch are '0'. Table 10 shows the power-save mode truth table. Figure 25 shows the power-save mode operation timing.

Output On/Off Data Write Timing and Output Control

When the 17-bit shift register MSB is '0', the output on/off data latch can be updated with the lower 16 bits of data in the shift register at the rising edge of the LAT signal, after the data are stored in the shift register using the SIN and SCLK signals. When the output on/off data latch is updated, SID (selected by the SIDLD bit) is loaded into the shift register, except when SIDLD = '00' (see [Table 6](#)). The output on/off data write timing is shown in [Figure 23](#).



- (1) On/off latch data is '1'.
- (2) On/off latch data change from '1' to '0' at second LAT signal.
- (3) On/off latch data is change from '0' to '1' at second LAT signal.
- (4) On/off latch data is '0'.

Figure 23. On/Off Data Write Timing

Function Control Data Writing

When the MSB is 1' in the 17-bit shift register, the control data latch can be updated with the lower 16 bits of data in the shift register at the rising edge of the LAT signal after the data are stored to the shift register using the SIN and SCLK signals. When the control data latch is updated, SID is not loaded into the shift register. The function control data write timing is shown in [Figure 24](#).

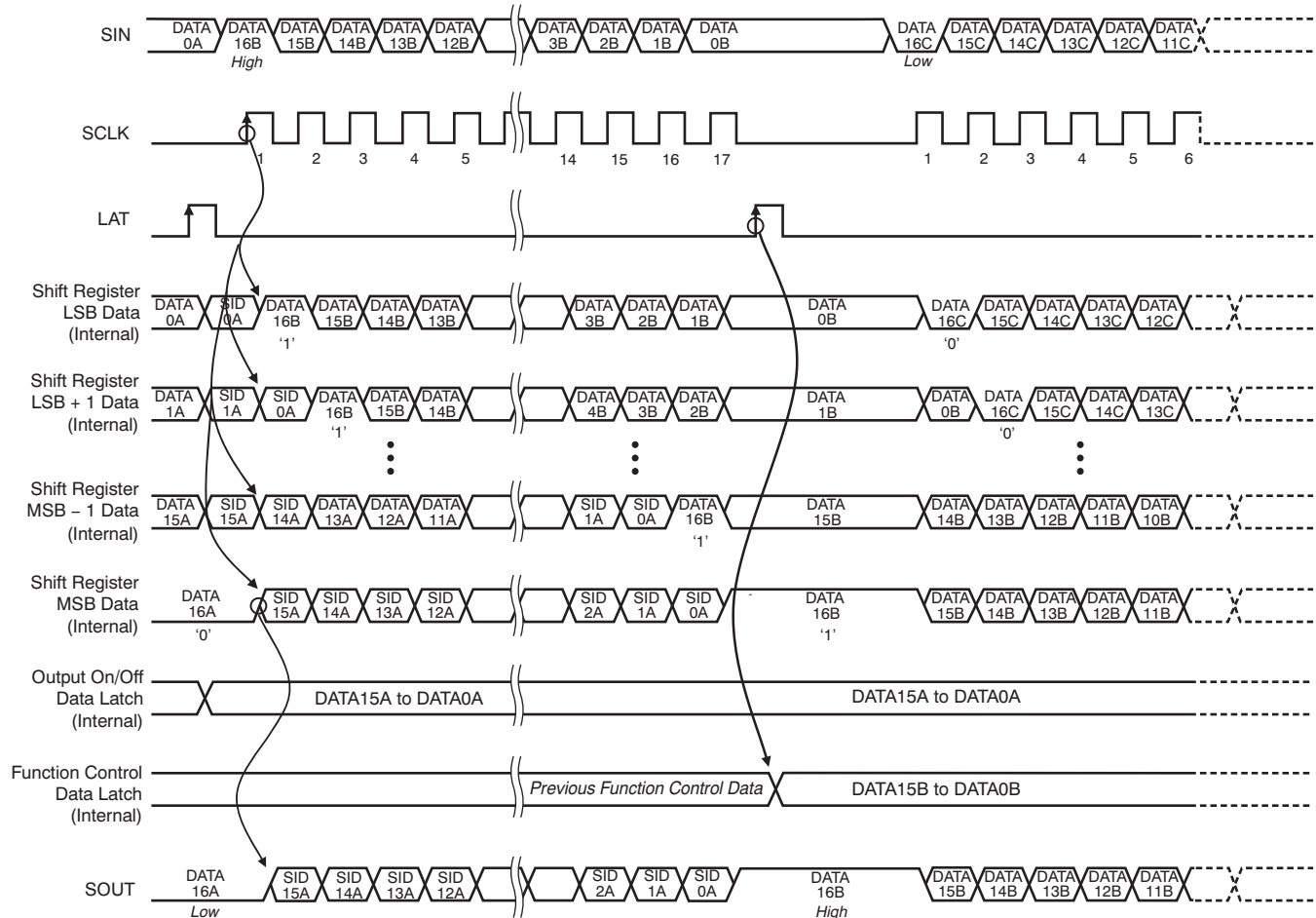


Figure 24. Function Control Data Write Timing

Function Control Data Bit Assignment

The function control data latch is 16 bits long and is used to adjust the output current values for LED brightness, SID selection, LSD voltage level, output current for IDM, output on-time for IDM, and power-save mode enable/disable. When the device powers on, the function control data latch is set to the default value (E67Fh). The function control data latch truth tables are shown in [Table 5](#) through [Table 10](#).

Table 5. Global Brightness Control (BC) Truth Table

BCALL BITS[6:0]	DESCRIPTION
0000000	Output current of OUT _n is set to $I_{OLCMax} \times 0\%$
0000001	$I_{OLCMax} \times 0.8\%$
...	...
1111110	$I_{OLCMax} \times 99.2\%$
1111111	$I_{OLCMax} \times 100\%$ (default value)

Table 6. SID Load Control Truth Table (see [Table 11](#) for more details)

SIDLD		STATUS INFORMATION DATA (SID) LOADED TO THE COMMON SHIFT REGISTER
BIT 8	BIT 7	
0	0	No data is loaded (default value)
0	1	LED open detection (LOD) or thermal error flag (TEF) data are loaded
1	0	LED short detection (LSD) or pre-thermal warning (PTW) data are loaded
1	1	Output leakage detection (OLD) or IREF pin short flag (ISF) data are loaded

Table 7. LSD Threshold Voltage Truth Table

LSDVLT		LED SHORT DETECTION (LSD) THRESHOLD VOLTAGE
BIT 10	BIT 9	
0	0	V_{LSD0} ($0.35 \times V_{CC}$ typ)
0	1	V_{LSD1} ($0.45 \times V_{CC}$ typ)
1	0	V_{LSD2} ($0.55 \times V_{CC}$ typ)
1	1	V_{LSD3} ($0.65 \times V_{CC}$ typ, default value)

Table 8. Current Select for IDM

IDMCUR		SINK CURRENT AT OUT _n FOR INVISIBLE DETECTION MODE (IDM)
BIT 12	BIT 11	
0	0	IDM is disabled (default value)
0	1	2 μ A (typ)
1	0	10 μ A (typ)
1	1	20 μ A (typ)

Table 9. IDM Work-Time Truth Table

IDMTIM		INVISIBLE DETECTION MODE (IDM) WORKING TIME
BIT 14	BIT 13	
0	0	All outputs are turned on for 17 OSC clocks (0.85 μ s typ)
0	1	All outputs are turned on for 33 OSC clocks (1.65 μ s typ)
1	0	All outputs are turned on for 65 OSC clocks (3.25 μ s typ)
1	1	All outputs are turned on for 129 OSC clocks (6.45 μ s typ, default value)

Table 10. Power-Save Mode Truth Table

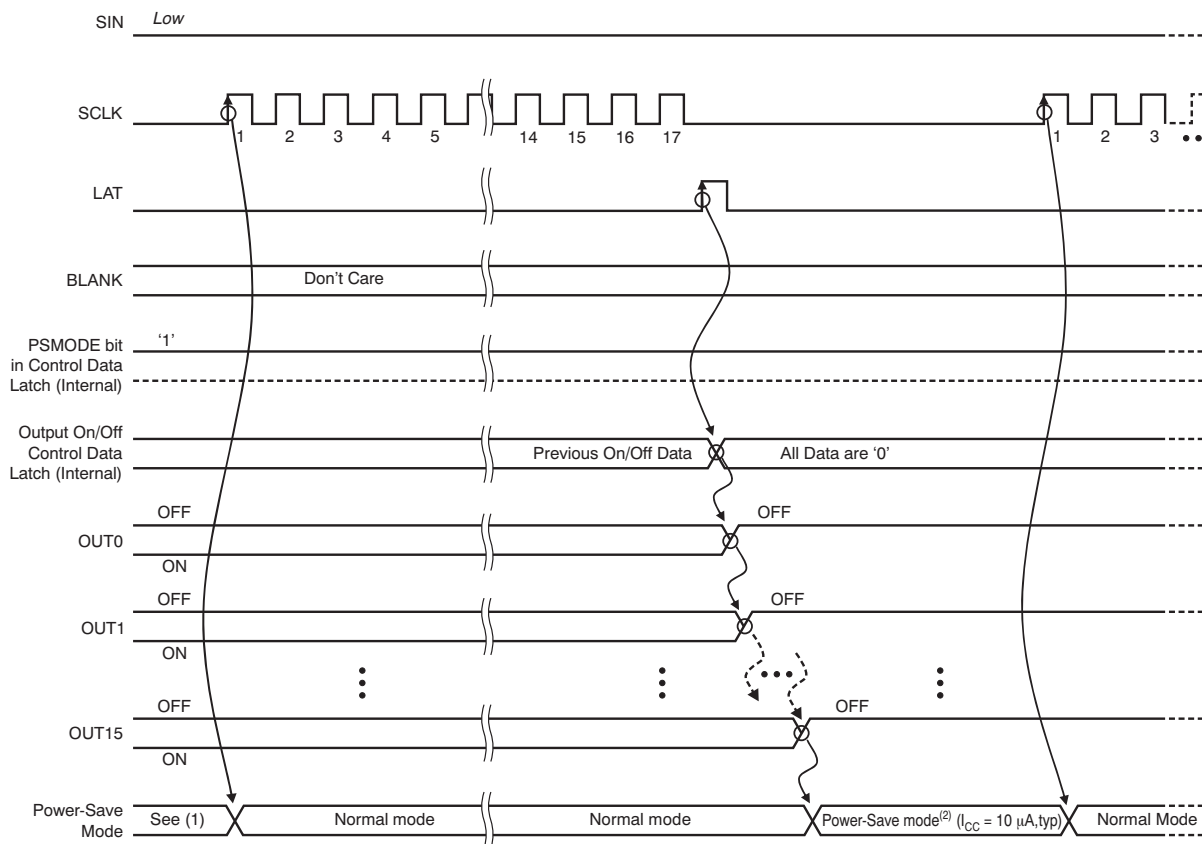
PSMODE	POWER-SAVE MODE FUNCTION
BIT 15	
0	Power-save mode is disabled. The device does not go into power-save mode even if the bits in the output on/off data latch are all '0'.
1	Power save mode is enabled (default value). The device goes into power-save mode when the bits in the output on/off data latch are all '0'.

Table 11. SID Load Assignment

SIDLD BIT (BINARY)	SELECTED DETECTOR	CHECKED OUT n	BIT NUMBER LOADED INTO COMMON SHIFT REGISTER	DESCRIPTION
00	No detector selected	—	No data loaded	The data in the common shift register are not changed.
01	LED open detection (LOD)	OUT0	0	The data in the common shift register are updated with LOD or TEF data.
		OUT1	1	All bits '1' = device junction temperature (T_J) is very high ($T_J > T_{TEF}$) and all outputs are forced off by the thermal shutdown function.
		...	...	
		OUT14	14	'1' = OUT n shows lower voltage than the LED open detection threshold (V_{LOD}).
		OUT15	15	'0' = normal operation.
10	LED short detection (LSD)	OUT0	0	The data in the common shift register are updated with LSD or PTW data.
		OUT1	1	All bits '1' = device junction temperature (T_J) is high ($T_J > T_{PTW}$).
		...	...	
		OUT14	14	'1' = OUT n shows higher voltage than the LED short detection threshold (V_{LSD}) selected by LSDVLT.
		OUT15	15	'0' = normal operation.
11	Output leakage detection (OLD)	OUT0	0	The data in the common shift register are updated with OLD or ISF data.
		OUT1	1	All bits '1' = IREF pin is shorted to GND with low impedance.
		...	...	'1' = OUT n is leaking to GND with greater than 3 μ A.
		OUT14	14	'0' = normal operation.
		OUT15	15	

POWER-SAVE MODE

In power-save mode, the TLC5929 input current becomes 10 μA (typ). When the PSMODE bit in the control data latch is '1', power-save mode is enabled. If the rising edge of LAT writes '0' into all bits of the output on/off data latch or any data into the control data latch with all bits of the on/off data latch being '0', the TLC5929 goes into power-save mode. The device stays in power-save mode until the next rising edge on SCLK is received. The power-save mode timing is shown in Figure 25.



(1) Contents depend on output on/off data.

(2) When PSMODE bit is '0', the device does not go into power-save mode even if the output on/off data is all '0'.

(3) Because it takes 20 μs (max) to return to normal mode, the first SCLK rising edge should be input at least 20 μs before OUT_n is enabled.

Figure 25. Power-Save Mode Timing

LED OPEN DETECTION (LOD)

LOD detects a fault caused by an open circuit in the n th LED string, or a short from OUT_n to ground, by comparing the OUT_n voltage to the LOD detection threshold voltage level ($V_{\text{LOD}} = 0.3 \text{ V}$, typ). If the OUT_n voltage is lower than V_{LOD} , that output LOD bit is set to '1' to indicate an open LED string. Otherwise, the LOD bit is set to '0'. LOD data are only valid for outputs that are programmed to be enabled. LOD data for outputs that are programmed to be disabled are always '0' (see Table 11), except when IDM is enabled.

The LOD data are stored in a 16-bit register called SID holder (see the [Functional Block Diagram](#)) at the rising edge of BLANK when the SIDLD bits are set to '01' (see Table 6). However, when the IDM is enabled, the LOD bits are stored in the SID holder at the end of the IDM working time selected by IDMTIM (see Table 9).

The stored LOD data can be read out through the common shift register as SID at the SOUT pin. LOD/LSID data are not valid for 0.5 μs after the output is turned on.

When the device resumes operation from power-save mode, the LOD cannot be executed before the propagation delay (t_{D4}) has elapsed because LOD does not work during power-save mode.

LED SHORT DETECTION (LSD)

The LSD data are stored into a 16-bit register called SID holder at the rising edge of BLANK when the SIDLD bits are set to '10' (see Table 6) or when IDM is enabled. The LSD bits are stored in the SID holder at the end of the IDM working time (IDMTIM). The stored LSD data can be read out through the common shift register as SID at the SOUT pin. Note that the LOD/LSD bits are not stable during the first 0.5 μ s after the falling edge of BLANK.

LSD data detect a fault caused by a shorted LED by comparing the OUT n voltage to the LSD detection threshold voltage level set by LSDVLT in the control data latch (see Table 4 and Table 7). If the OUT n voltage is higher than the programmed voltage, the corresponding output LSD bit is set to '1' to indicate a shorted LED. Otherwise, the LSD bit is set to '0'. LSD data are only valid for outputs that are programmed to be enabled. LSD data for outputs that are programmed to be disabled are always '0' (see Table 11), except when IDM is enabled. When the device resumes operation from the power-save mode, LSD cannot be executed before the propagation delay (t_{D4}) has elapsed because LSD does not work during power-save mode.

INVISIBLE DETECTION MODE (IDM)

Invisible detection mode (IDM) can detect LOD and LSD even when the output on/off data are set to the off state. When the IDMCUR bits in the control data latch are set to any value except '00', all outputs start sinking the current set by the IDMCUR bits at the falling edge of BLANK and stop sinking the current at the rising edge of BLANK, or the time set by IDMTIM has elapsed. When OUT n stops, the selected SID data by SIDLD bits are latched into the SID holder.

When the IDMCUR bits in the control data latch are set to '00', IDM is disabled.

Figure 26 shows the LOD/LSD/OLD/IDM circuits. Figure 27 and Figure 28 illustrate the IDM operation timing and Table 12 shows a truth table for LOD/LSD/OLD.

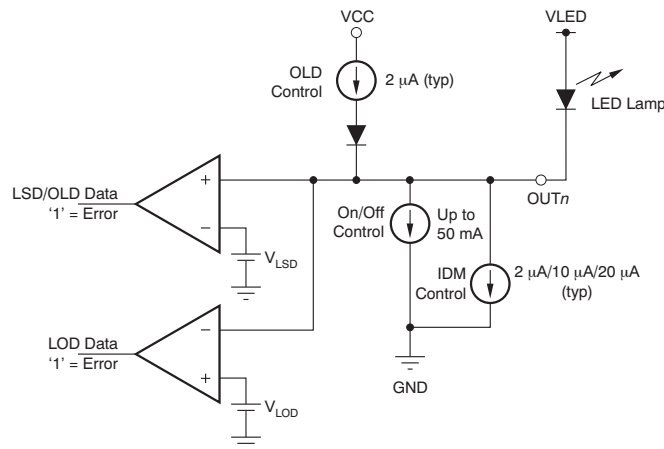


Figure 26. LOD/LSD/OLD/IDM Circuit

Table 12. LOD/LSD/OLD Truth Table

LOD	LSD	OLD	CORRESPONDING BIT IN SID
LED is not opened ($V_{OUTn} > V_{LoD}$)	LED is not shorted ($V_{OUTn} \leq V_{LSd}$)	OUT n does not leak to GND ($V_{OUTn} > V_{LSd}$ when constant-current output off and OUT n source current on)	0
LED is open or shorted to GND ($V_{OUTn} \leq V_{LoD}$)	LED is shorted between anode and cathode, or shorted to higher voltage side ($V_{OUTn} > V_{LSd}$)	Current leaks from OUT n to internal GND, or OUT n is shorted to external GND with high impedance ($V_{OUTn} \leq V_{LSd}$ when constant-current output off and OUT n source current on)	1

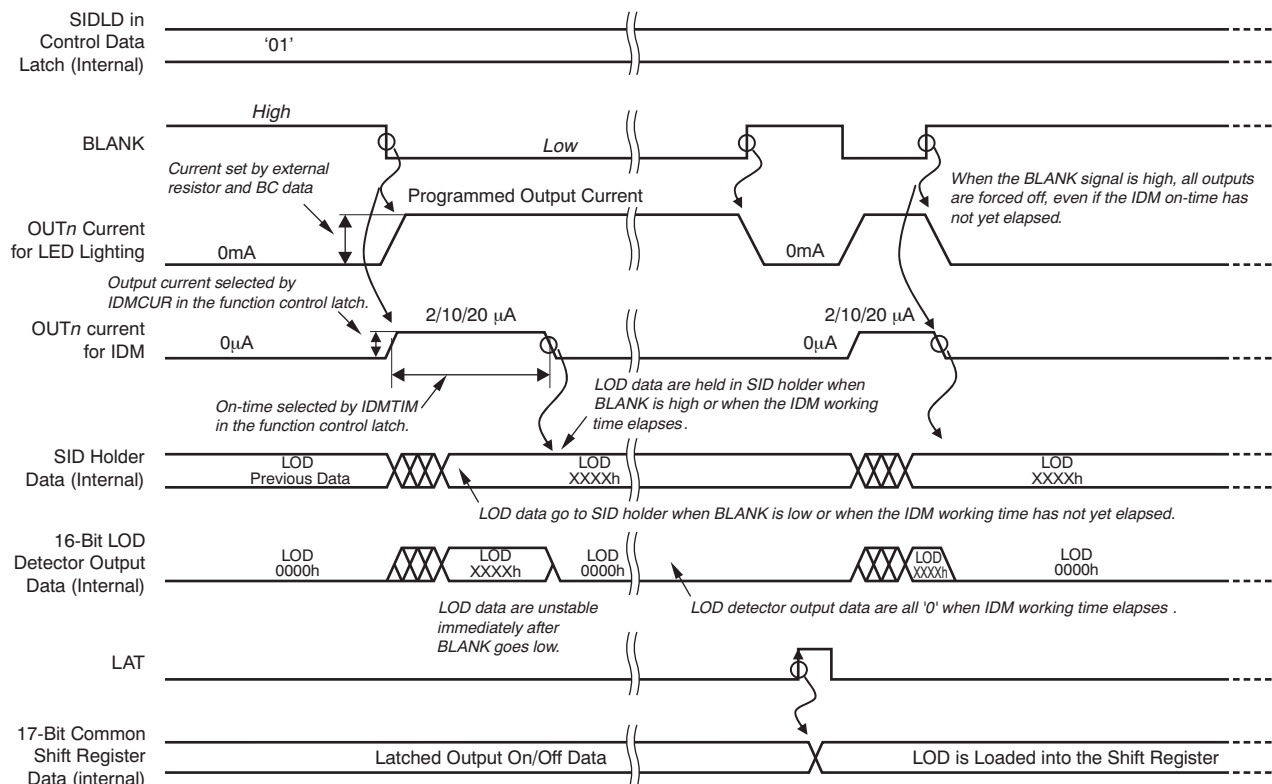


Figure 27. IDM Operation Timing with LOD Selected and IDM Enabled

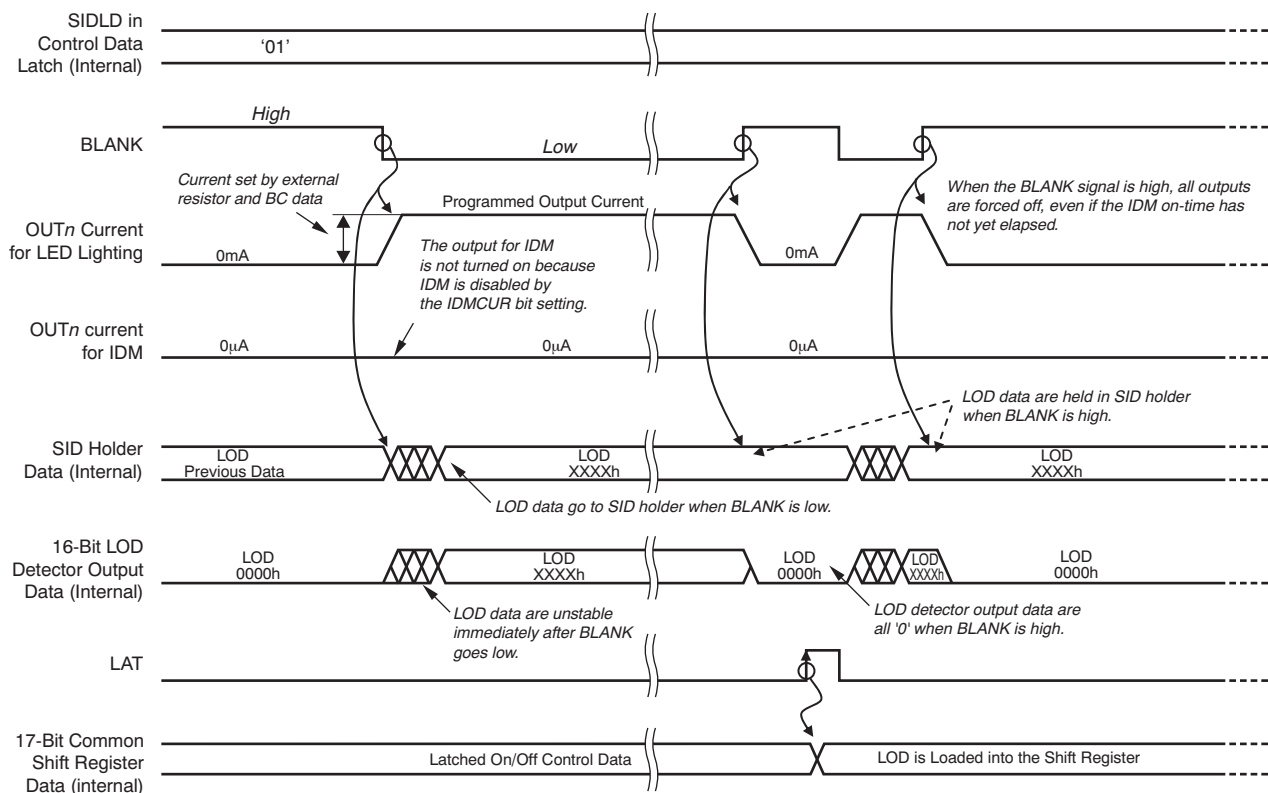


Figure 28. IDM Operation Timing with LOD Selected and IDM Disabled

OUTPUT LEAKAGE DETECTION (OLD)

When IDM mode is enabled, OLD is always disabled.

Output leakage detection (OLD) detects a fault caused by a short with high resistance from OUT_n to GND by comparing the OUT_n voltage to the LSD detection threshold voltage when the output on/off data are set to the off state. OLD can also detect a short between adjacent pins. A very small current is sourced from the turned-off OUT_n to detect leaking when the SIDLD bits are '11' and BLANK is low. OLD operation is disabled when the SIDLD bits are set to any value except '11', and then the current source is stopped. If the OUT_n voltage is lower than the programmed LSD threshold voltage, the corresponding OLD bit is set to '1' to indicate a leaking LED. Otherwise, the OLD bit is set to '0'. The OLD result is valid for disabled outputs only. The OLD data are latched into the SID holder when BLANK goes high. The OLD bits of the enabled outputs are always '0'. When the device resumes operation from power-save mode, OLD cannot be executed until after the propagation delay (t_{D4}) has elapsed because OLD does not work during power-save mode.

STATUS INFORMATION DATA (SID)

The status information data (SID) contains the status of the LED open detection (LOD), LED short detection (LSD), output leakage detection (OLD), pre-thermal warning (PTW), thermal error flag (TEF), and IREF short flag (ISF), depending on the SIDLD bits in the control data latch. When the MSB of the common shift register is set to '0', the selected SID overwrite the lower 16 bits in the common shift register at the rising edge of LAT after the data in the common shift register are copied to the output on/off data latch. If the MSB of the common shift register is '1', the data in the common shift register do not change.

After being copied into the common shift register, new SID data are not available until new data are written into the common shift register. If new data are not written, the LAT signal is ignored. To recheck SID without changing the on/off control data, reprogram the common shift register with the same data currently programmed into the on/off data latch. When LAT goes high, the output on/off data do not change, but new SID data are loaded into the common shift register. LOD, LSD, OLD, PTW, TEF, and ISF are shifted out of SOUT with each rising edge of SCLK.

The SID reading must be delayed for a duration of t_{D4} or more after the device resumes operation from the power-save mode because SID does not indicate correct data during the power-save mode. The SID load configuration and SID read timing are shown in Figure 29 and Figure 30, respectively.

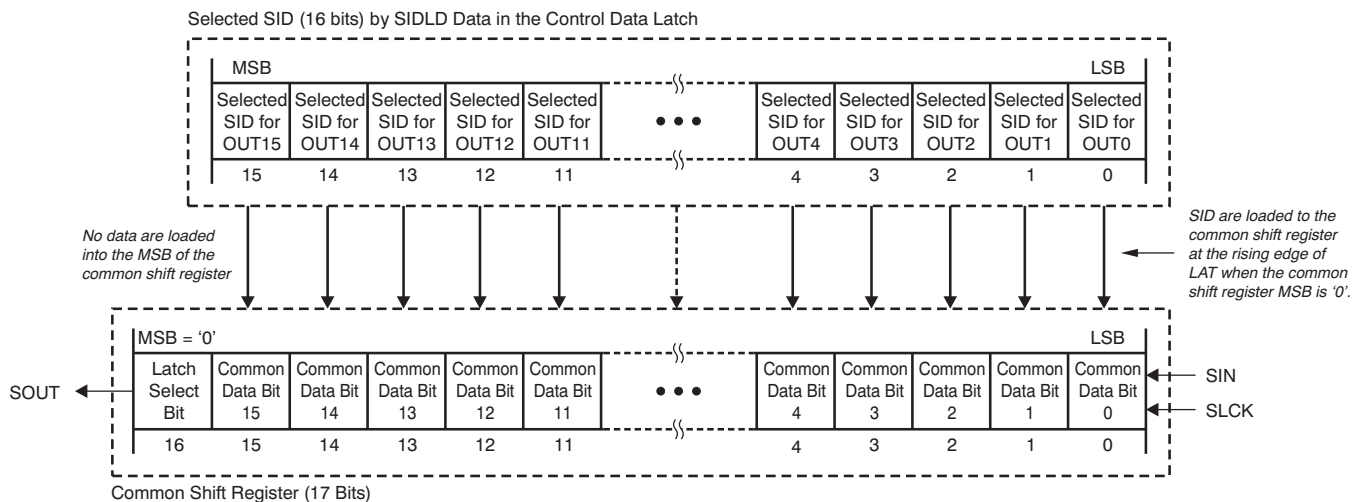


Figure 29. SID Load Configuration

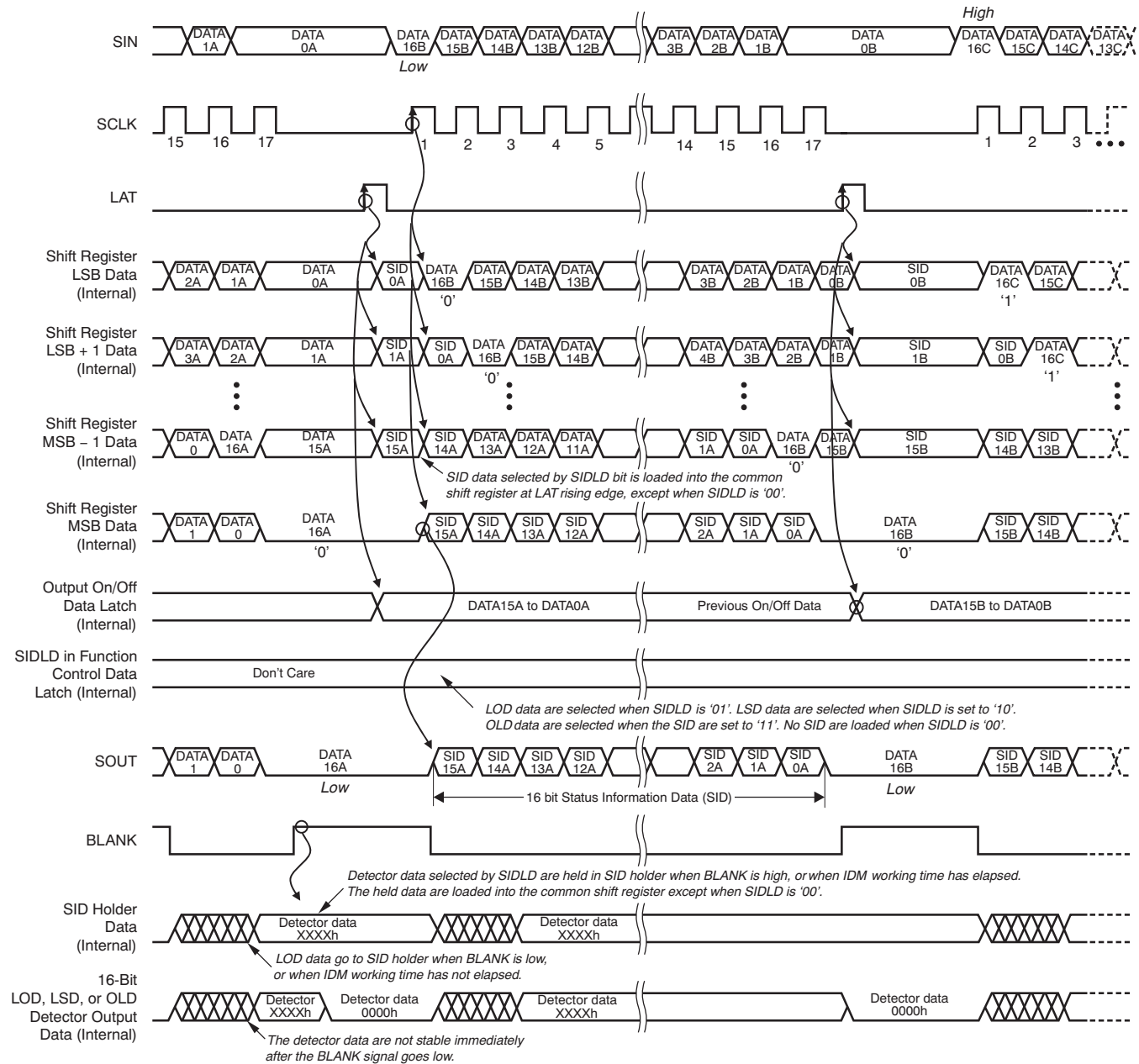


Figure 30. SID Read Timing

THERMAL SHUTDOWN (TSD) AND THERMAL ERROR FLAG (TEF)

The thermal shutdown (TSD) function turns off all constant-current outputs when the junction temperature (T_J) exceeds the threshold ($T_{TEF} = +165^\circ\text{C}$, typ) and sets all LOD data bits to '1'. When the junction temperature drops below ($T_{TEF} - T_{HYST}$), the output control starts normally. The TEF remains '1' until the next rising edge on LAT even if the temperature drops below the low level. Figure 31 shows the timing diagram and Table 13 shows the truth table for TEF.

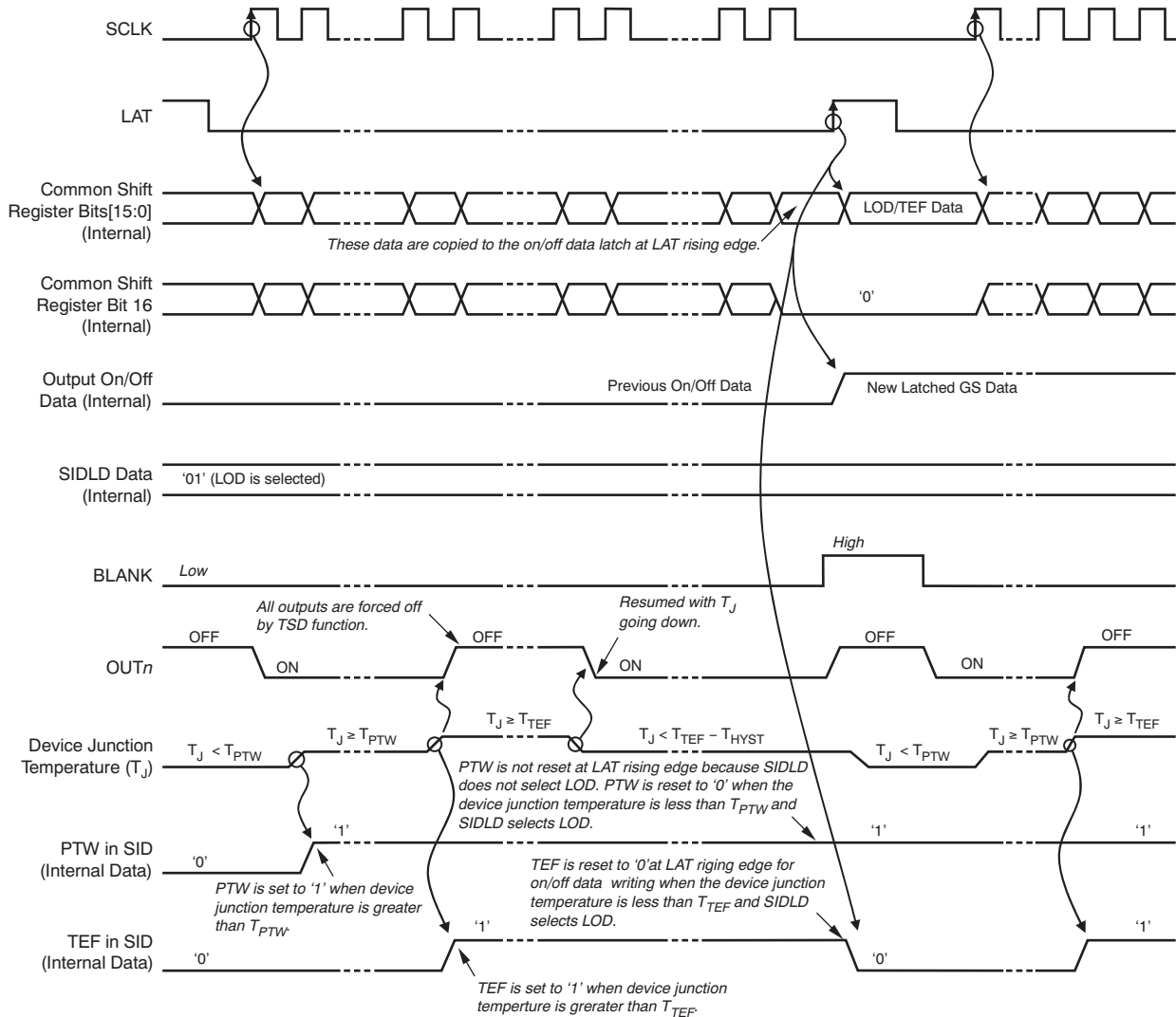


Figure 31. TEF/PTW/ISF Timing (LOD selected)

Table 13. TEF/PTW/ISF Truth Table

TEF	PTW	ISF	CORRESPONDING DATA BITS IN SID
Device temperature is lower than high-side detect temperature (temperature $\leq T_{TEF}$)	Device temperature is lower than pre-thermal warning temperature (temperature $\leq T_{PTW}$)	IREF terminal is not shorted	Depends on LOD/LSD/OLD
Device temperature is higher than high-side detect temperature and all outputs are forced off (temperature $> T_{TEF}$)	Device temperature is higher than pre-thermal warning temperature (temperature $> T_{PTW}$)	IREF terminal is shorted to GND with low impedance and all outputs (OUT0 to OUT15) are forced off	SID is all 1s for TEF when SIDLD bit = '01'. SID is all 1s for PTW when SIDLD = '10'. SID is all 1s for ISF when SIDLD = '11'.

PRE-THERMAL WARNING (PTW)

The PTW function indicates that the device junction temperature is high. The PTW is set and all LSD data bits are set to '1' while the device junction temperature exceeds the temperature threshold ($T_{PTW} = +138^{\circ}\text{C}$, typ); however, the outputs are not forced off. When the PTW indicates a high temperature, the device temperature should be reduced by lowering the power dissipated in the driver to avoid a forced shutdown by the thermal shutdown circuit. This reduction can be accomplished by lowering the values of the BC data or the LED supply voltage. The PTW remains '1' until the next rising edge on LAT, even if the temperature drops below T_{PTW} . [Figure 31](#) shows a timing diagram and [Table 13](#) shows the truth table for PTW.

CURRENT REFERENCE (IREF PIN) SHORT FLAG (ISF)

The ISF function indicates that the IREF pin is shorted with low impedance to GND. When ISF is set, all OLD data bits are set to '1'. Then all outputs (OUT_n) are forced off and remain off until the short is removed. [Table 13](#) shows the truth table for ISF.

NOISE REDUCTION

Large surge currents may flow through the device and the board on which the device is mounted if all 16 outputs turn on simultaneously when BLANK goes low or on/off data change at the LAT rising edge with BLANK low. These large current surges could introduce detrimental noise and electromagnetic interference (EMI) into other circuits. The TLC5929 turns the outputs on with a 2-ns series delay for each output in order to provide a circuit soft-start feature.

REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision A (September 2011) to Revision B	Page
• Deleted application bullet	1
• Updated text in Table 6 (typo)	22

Changes from Original (April 2011) to Revision A	Page
• Added maximum values to Constant-Current Accuracy feature sub-bullets	1
• Added new RGE (QFN-24) package to Package/Ordering Information table	2
• Added new RGE (QFN-24) package to Thermal Information table	2
• Added new RGE (QFN-24) pinout	10
• Added new RGE (QFN-24) package to Pin Descriptions table	11

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TLC5929DBQ	Active	Production	SSOP (DBQ) 24	50 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	TLC5929
TLC5929DBQ.B	Active	Production	SSOP (DBQ) 24	50 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	TLC5929
TLC5929DBQR	Active	Production	SSOP (DBQ) 24	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	TLC5929
TLC5929DBQR.B	Active	Production	SSOP (DBQ) 24	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	TLC5929
TLC5929PWP	Active	Production	HTSSOP (PWP) 24	60 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	PJ5929
TLC5929PWP.B	Active	Production	HTSSOP (PWP) 24	60 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	PJ5929
TLC5929PWPR	Active	Production	HTSSOP (PWP) 24	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	PJ5929
TLC5929PWPR.B	Active	Production	HTSSOP (PWP) 24	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	PJ5929
TLC5929RGER	Active	Production	VQFN (RGE) 24	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	TLC 5929
TLC5929RGER.B	Active	Production	VQFN (RGE) 24	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	TLC 5929
TLC5929RGERG4	Active	Production	VQFN (RGE) 24	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	TLC 5929
TLC5929RGERG4.B	Active	Production	VQFN (RGE) 24	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	TLC 5929
TLC5929RGET	Active	Production	VQFN (RGE) 24	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	TLC 5929
TLC5929RGET.B	Active	Production	VQFN (RGE) 24	250 SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	TLC 5929

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

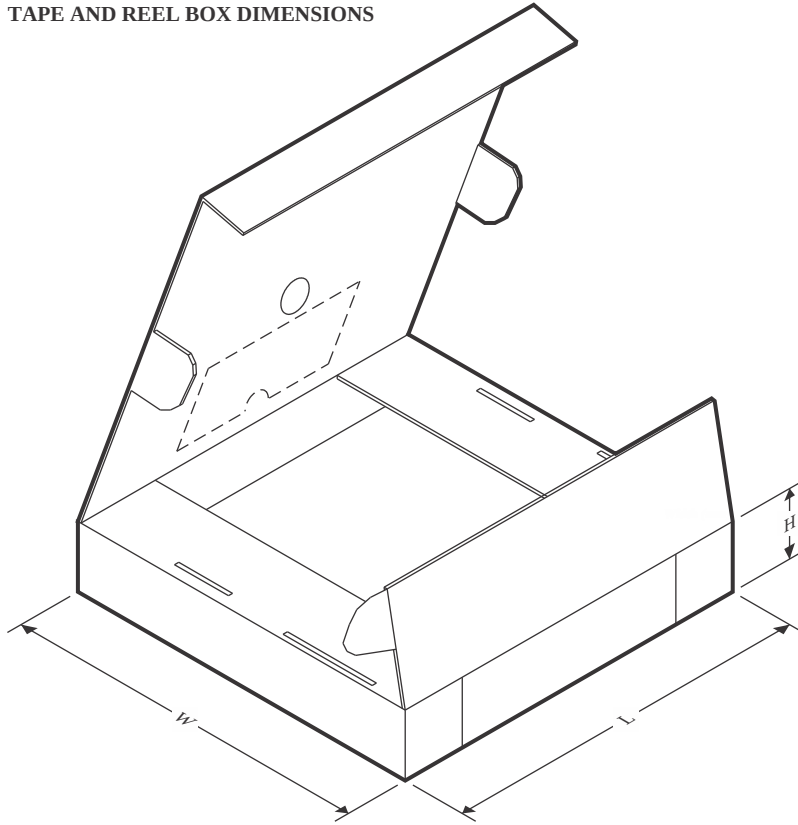
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC5929DBQR	SSOP	DBQ	24	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TLC5929PWPR	HTSSOP	PWP	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
TLC5929RGER	VQFN	RGE	24	3000	330.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2
TLC5929RGERG4	VQFN	RGE	24	3000	330.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2
TLC5929RGET	VQFN	RGE	24	250	180.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2

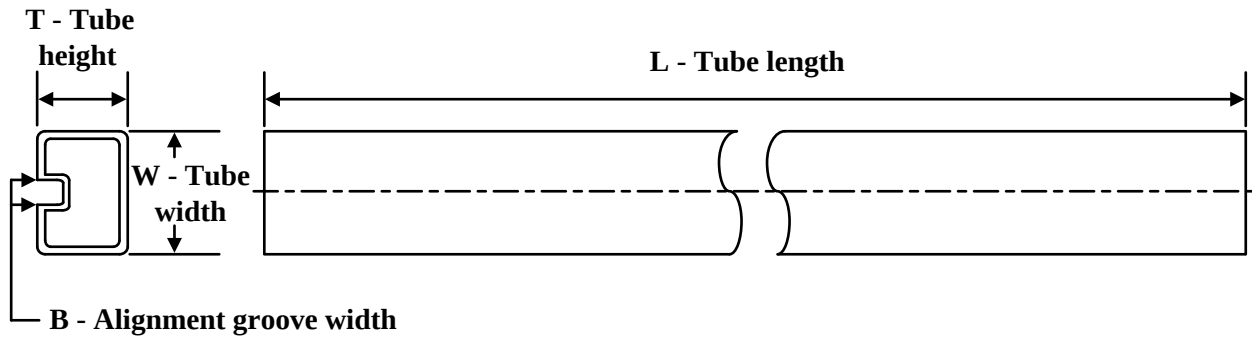
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC5929DBQR	SSOP	DBQ	24	2500	353.0	353.0	32.0
TLC5929PWPR	HTSSOP	PWP	24	2000	353.0	353.0	32.0
TLC5929RGER	VQFN	RGE	24	3000	353.0	353.0	32.0
TLC5929RGERG4	VQFN	RGE	24	3000	353.0	353.0	32.0
TLC5929RGET	VQFN	RGE	24	250	213.0	191.0	35.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
TLC5929DBQ	DBQ	SSOP	24	50	506.6	8	3940	4.32
TLC5929DBQ.B	DBQ	SSOP	24	50	506.6	8	3940	4.32
TLC5929PWP	PWP	HTSSOP	24	60	530	10.2	3600	3.5
TLC5929PWP.B	PWP	HTSSOP	24	60	530	10.2	3600	3.5

GENERIC PACKAGE VIEW

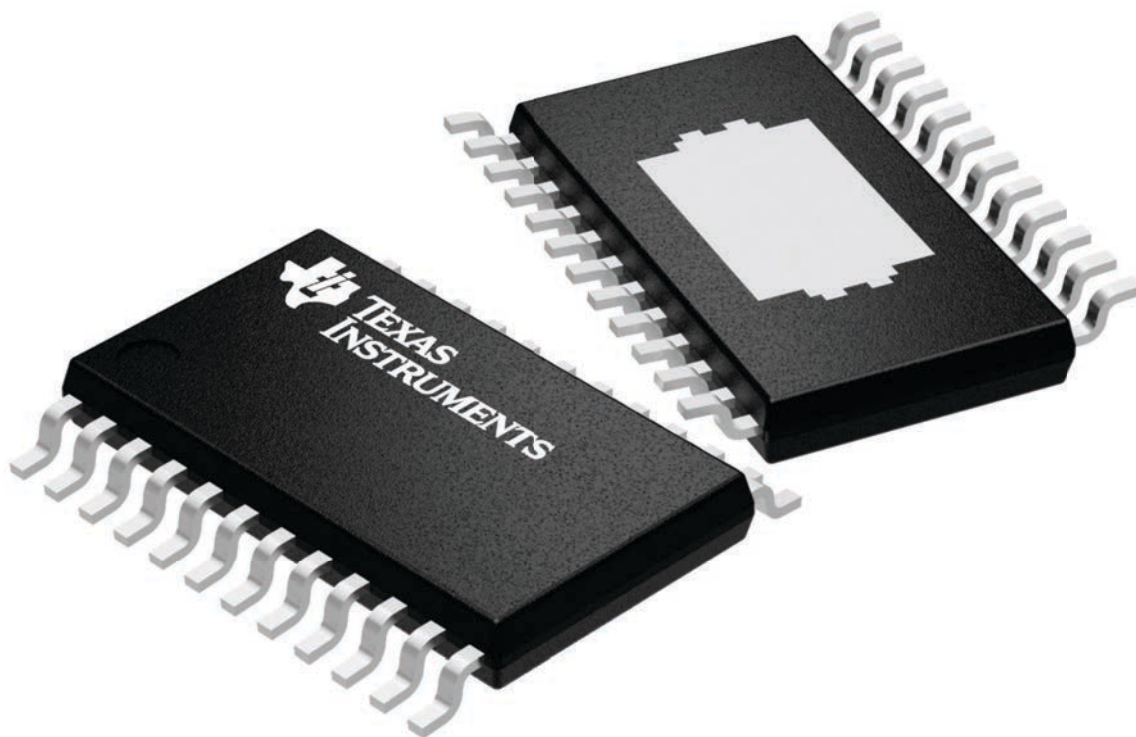
PWP 24

PowerPAD™ TSSOP - 1.2 mm max height

4.4 x 7.6, 0.65 mm pitch

PLASTIC SMALL OUTLINE

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4224742/B



PowerPAD™ TSSOP - 1.2 mm max height

PLASTIC SMALL OUTLINE



PowerPAD is a trademark of Texas Instruments.

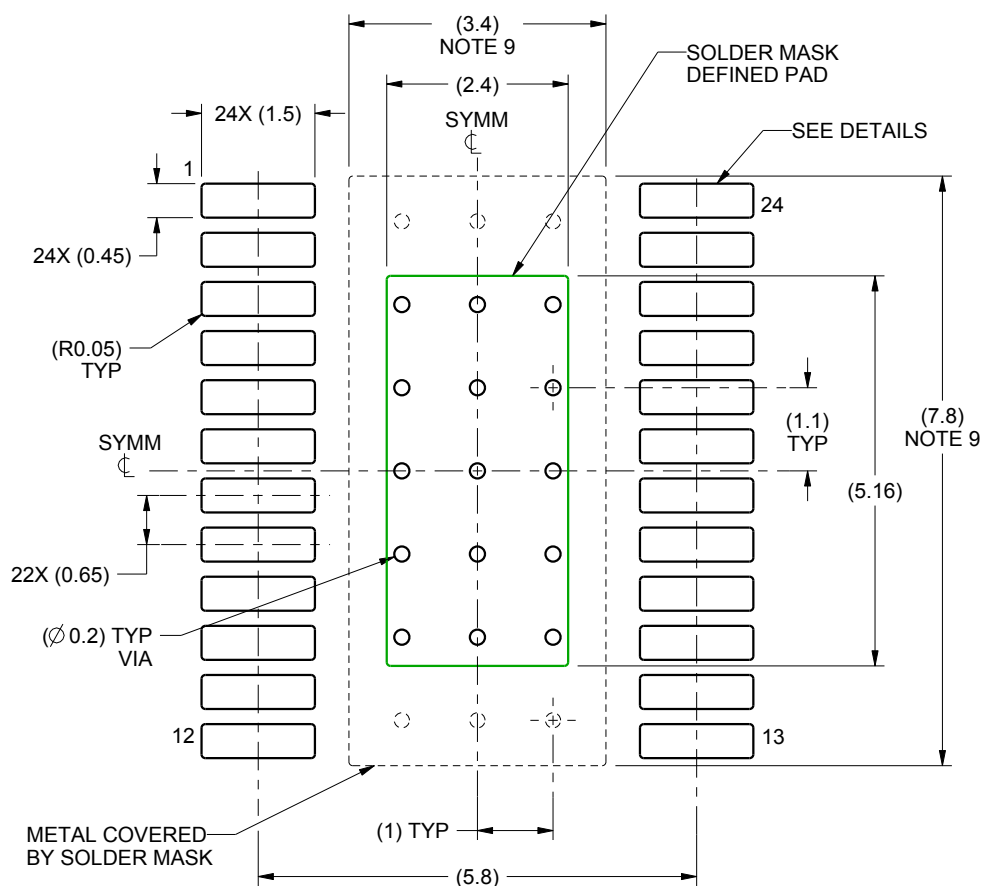
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.
5. Features may not be present and may vary.

EXAMPLE BOARD LAYOUT

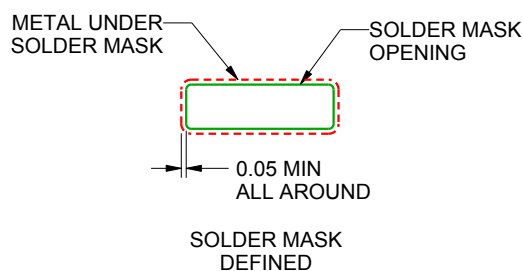
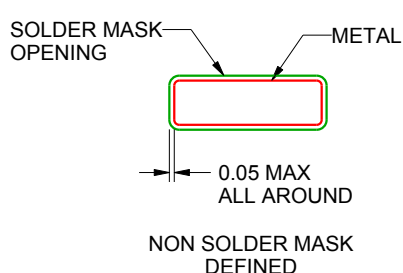
PWP0024B

PowerPAD™ TSSOP - 1.2 mm max height

PLASTIC SMALL OUTLINE



LAND PATTERN EXAMPLE
SCALE:10X



SOLDER MASK DETAILS
PADS 1-24

4222709/A 02/2016

NOTES: (continued)

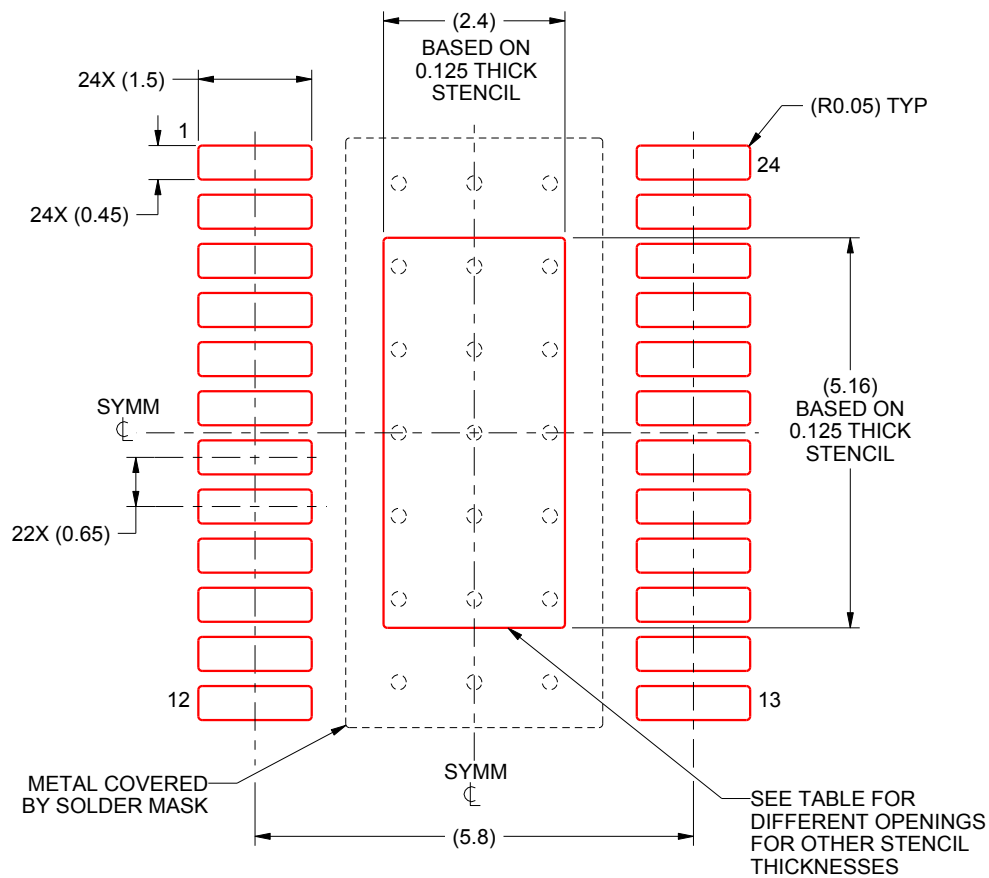
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
9. Size of metal pad may vary due to creepage requirement.

EXAMPLE STENCIL DESIGN

PWP0024B

PowerPAD™ TSSOP - 1.2 mm max height

PLASTIC SMALL OUTLINE



SOLDER PASTE EXAMPLE
EXPOSED PAD
100% PRINTED SOLDER COVERAGE BY AREA
SCALE:10X

STENCIL THICKNESS	SOLDER STENCIL OPENING
0.1	2.68 X 5.77
0.125	2.4 X 5.16 (SHOWN)
0.15	2.19 X 4.71
0.175	2.03 X 4.36

4222709/A 02/2016

NOTES: (continued)

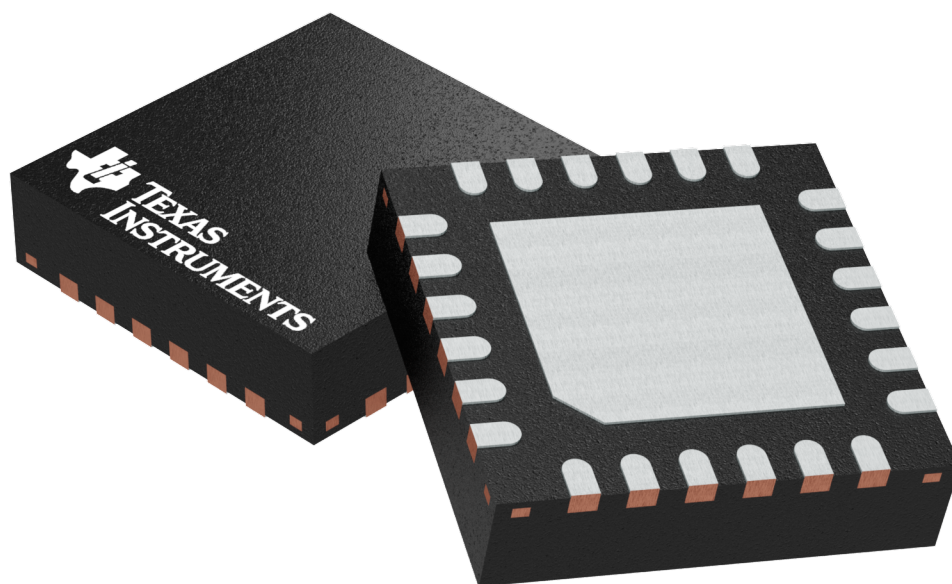
10. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
11. Board assembly site may have different recommendations for stencil design.

RGE 24

GENERIC PACKAGE VIEW

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4204104/H



VQFN - 1 mm max height

The drawing shows a 24-pin connector with the following features and dimensions:

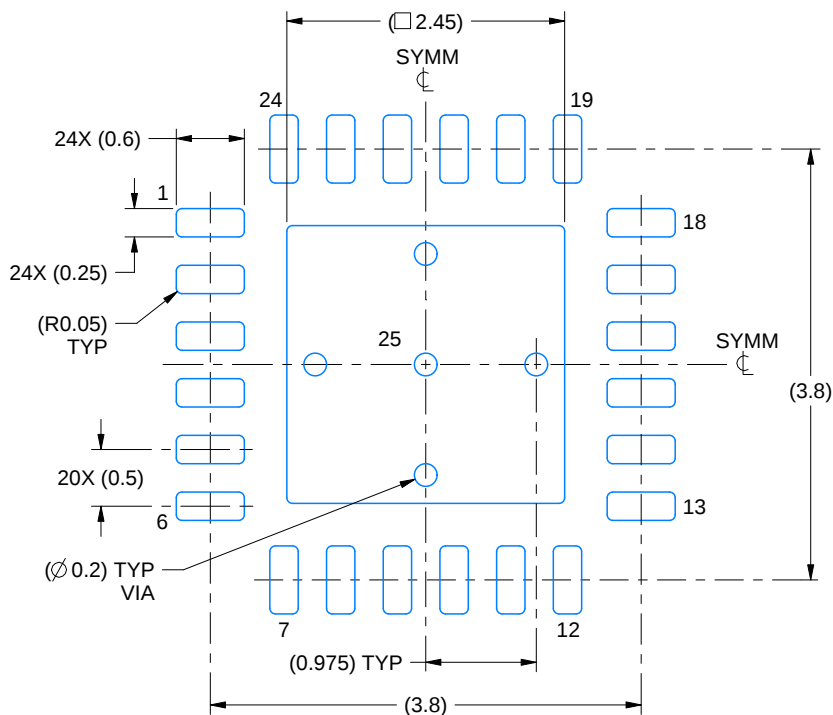
- Top View:**
 - Overall width: 4.1 (3.9)
 - Overall height: 4.1 (3.9)
 - PIN 1 INDEX AREA:** A shaded rectangular area in the top-left corner.
 - DETAIL OPTIONAL TERMINAL TYPICAL:** A cross-sectional view of a terminal with dimensions 0.5, 0.3, 0.3, and 0.2.
- Side View:**
 - Maximum height: 1 MAX
 - Terminal thickness: 0.05 (0.00)
 - SEATING PLANE:** Indicated by a triangle and a horizontal line.
 - Feature C:** A semi-circular feature with a radius of 0.08.
- Bottom View:**
 - SEE TERMINAL DETAIL:** Points to the terminal profile.
 - 24X 2.5:** Dimension for the terminal pitch.
 - 20X 0.5:** Dimension for the terminal width.
 - PIN 1 ID (OPTIONAL):** Points to the pin 1 identification mark.
 - EXPOSED THERMAL PAD:** A central square area with a side length of 2.5.
 - SYMM:** Symmetry markers.
 - 24X 0.5 (0.3):** Dimension for the terminal width.
 - 24X 0.3 (0.2):** Dimension for the terminal pitch.
 - Feature C:** A semi-circular feature with a radius of 0.08.
- Right View:**
 - (0.2) TYP:** Typical dimension for the terminal thickness.

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

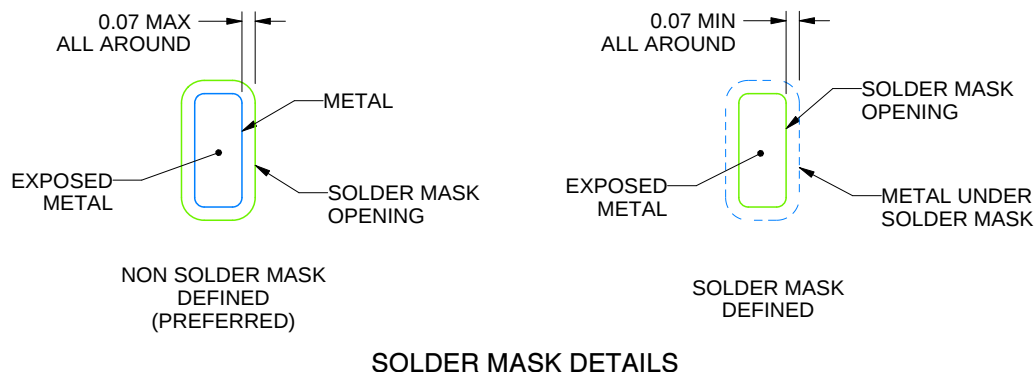
RGE0024B

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X



4219013/A 05/2017

NOTES: (continued)

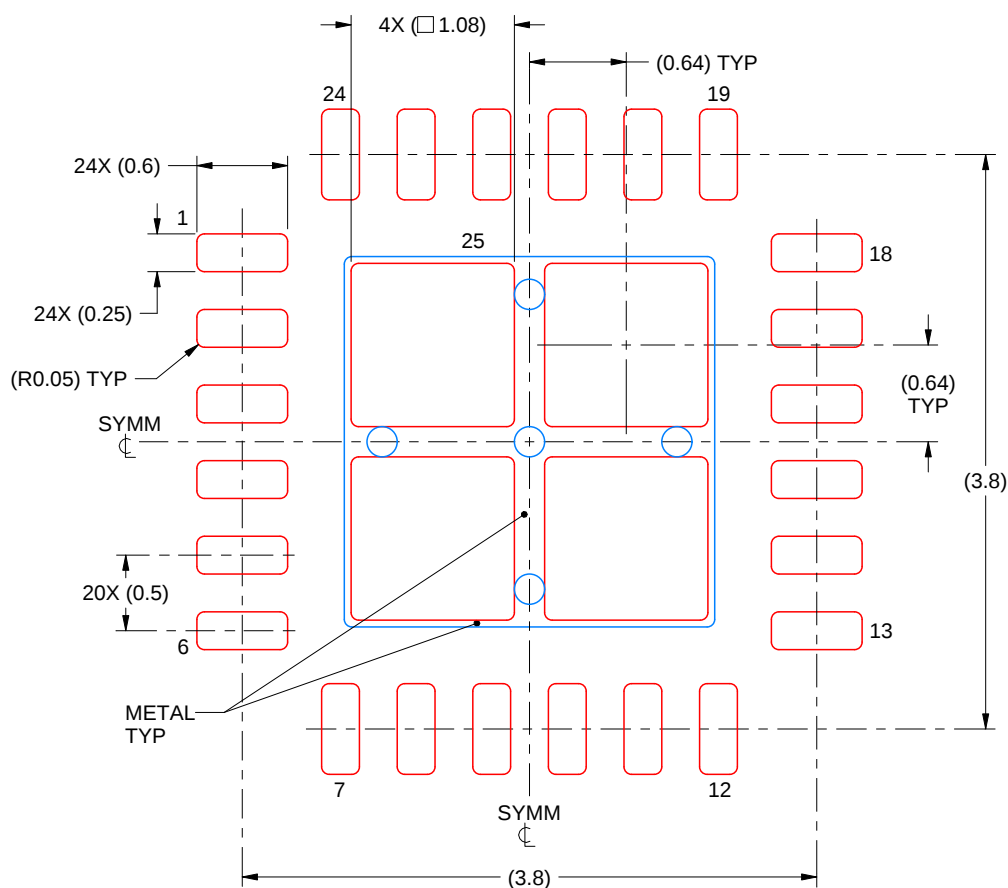
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

RGE0024B

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 25
78% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:20X

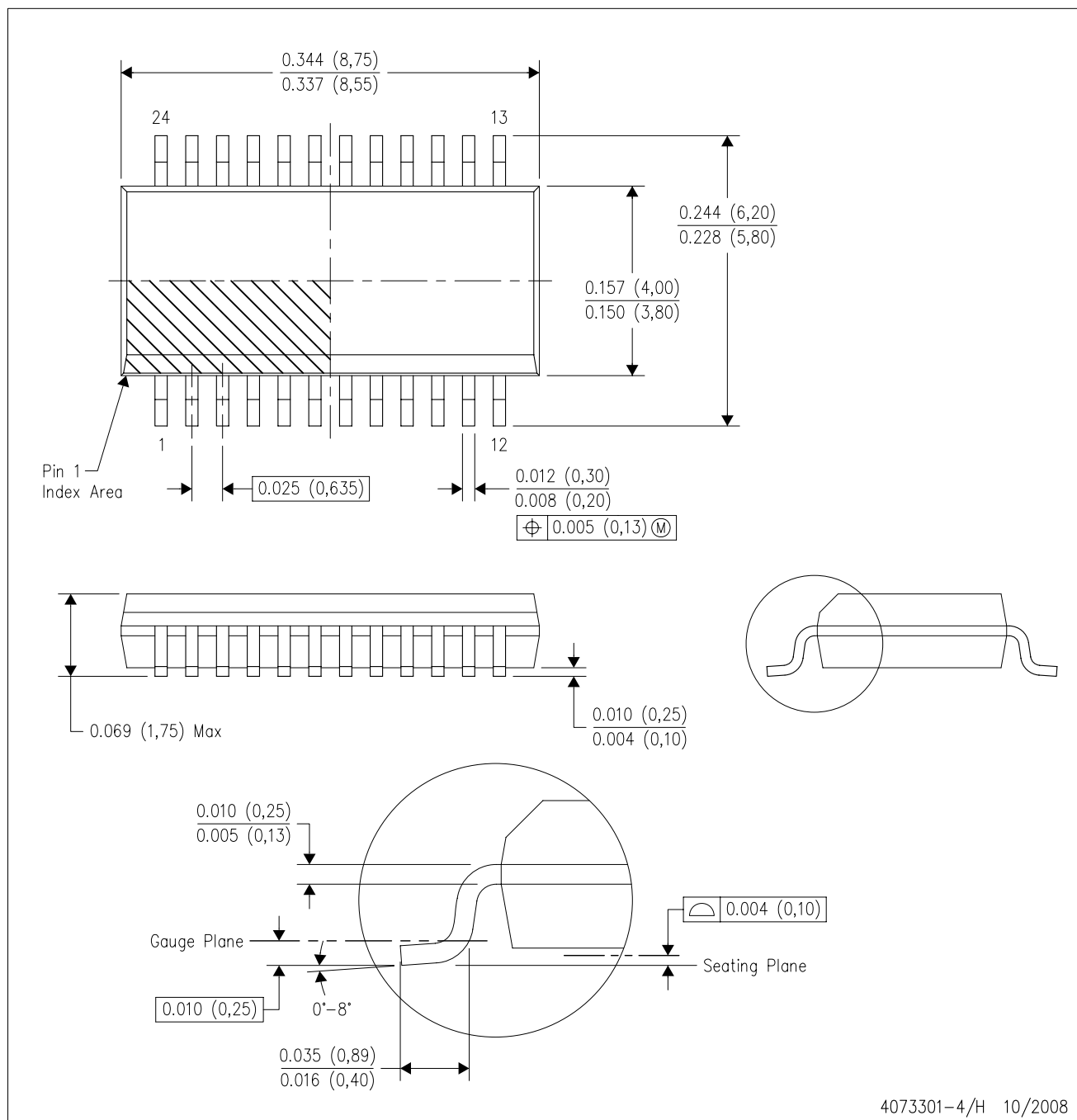
4219013/A 05/2017

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

DBQ (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
 - Falls within JEDEC MO-137 variation AE.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#), [TI's General Quality Guidelines](#), or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2026, Texas Instruments Incorporated

Last updated 10/2025